

# ADS7057 14 位, 2.5 MSPS, 差分输入, 小型低功耗 SAR ADC

## 1 特性

- 2.5 MSPS 吞吐量
- 封装尺寸小:
  - X2QFN-8 封装 (1.5mm × 1.5mm)
- 全差动输入范围:  $\pm AVDD$
- 宽工作电压范围:
  - AVDD: 2.35V 至 3.6V
  - DVDD: 1.65V 至 3.6V (与 AVDD 无关)
  - 温度范围: -40°C 至 +125°C
- 性能优异:
  - 14 位 NMC DNL,  $\pm 0.9$ -LSB INL
  - 79.5dB SINAD (2kHz 时)
  - 77dB SINAD (1MHz 时)
- 低功耗:
  - 3.6mW (2.5 MSPS, 3.3V AVDD 时)
  - 160 $\mu$ W (100kSPS, 3.3V AVDD 时)
  - 82 $\mu$ W (100kSPS, 2.5V AVDD 时)
- 集成失调电压校准
- 与 SPI 兼容的串行接口: 60MHz
- 符合 JESD8-7A 标准的数字 I/O

## 2 应用

- 光学编码器
- 声纳接收器
- 探鱼器
- I/Q 解调器
- 光线路卡和模块
- 热成像摄像机
- 超声波流量计
- 手持无线电

## 3 说明

ADS7057 器件属于引脚对引脚兼容的高速低功耗、单通道逐次逼近型寄存器 (SAR) 类型的模数转换器 (ADC) 系列。该器件系列包含多个分辨率、吞吐量和模拟输入型号 (有关器件列表, 请参阅 [表格1](#))。

ADS7057 是一款 14 位 2.5 MSPS SAR ADC, 支持  $\pm AVDD$  范围内的全差分输入, AVDD 的范围为 2.35V 至 3.6V。

内部失调电压校准功能在整个 AVDD 和工作温度范围内可保持优异的失调电压规格。

该器件支持由  $\overline{CS}$  和 SCLK 信号控制的兼容 SPI 的串行接口。输入信号通过  $\overline{CS}$  下降沿进行采样, 而 SCLK 用于转换和串行数据输出。该器件支持宽数字电源范围 (1.65V 至 3.6V), 可直接连接到各种主机控制器。

ADS7057 的标称 DVDD 范围 (1.65V 至 1.95V) 符合 JESD8-7A 标准。

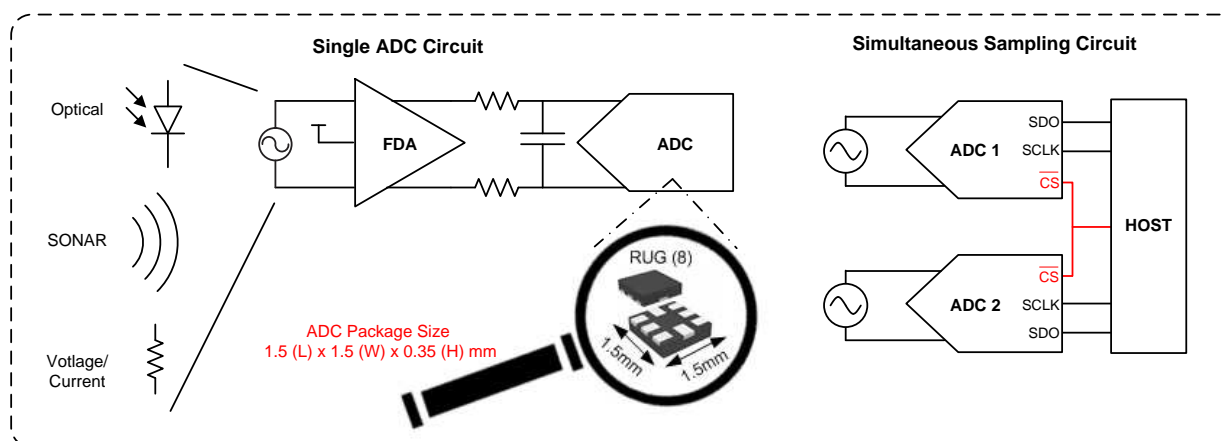
ADS7057 采用 8 引脚小型 X2QFN 封装, 可以在广泛的工业温度范围 (-40°C 至 +125°C) 内正常工作。该器件体积小, 功耗极低, 非常适合需要高速高分辨率数据采集的空间受限型 电池供电 应用。

器件信息<sup>(1)</sup>

部件名称	封装	封装尺寸 (标称值)
ADS7057	X2QFN (8)	1.50mm x 1.50mm

(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。

## 典型应用



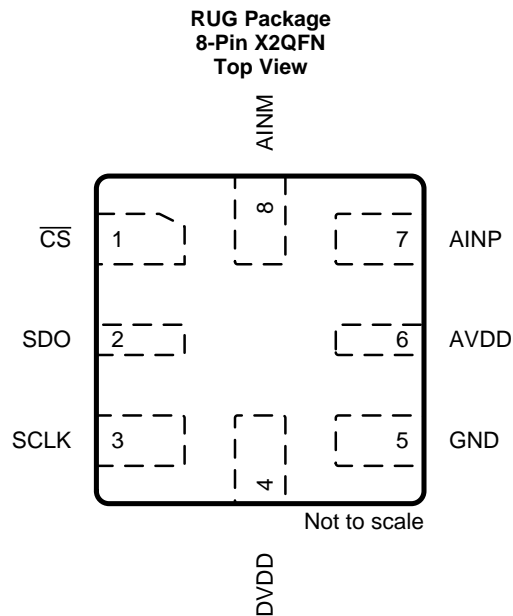
## 目录

<b>1</b>	特性 .....	<b>1</b>	8.4	Device Functional Modes.....	<b>20</b>
<b>2</b>	应用 .....	<b>1</b>	<b>9</b>	<b>Application and Implementation</b> .....	<b>24</b>
<b>3</b>	说明 .....	<b>1</b>	9.1	Application Information.....	<b>24</b>
<b>4</b>	修订历史记录 .....	<b>2</b>	9.2	Typical Applications .....	<b>24</b>
<b>5</b>	<b>Pin Configuration and Functions</b> .....	<b>3</b>	<b>10</b>	<b>Power Supply Recommendations</b> .....	<b>29</b>
<b>6</b>	<b>Specifications</b> .....	<b>4</b>	10.1	AVDD and DVDD Supply Recommendations.....	<b>29</b>
6.1	Absolute Maximum Ratings .....	<b>4</b>	10.2	Optimizing Power Consumed by the Device .....	<b>29</b>
6.2	ESD Ratings.....	<b>4</b>	<b>11</b>	<b>Layout</b> .....	<b>30</b>
6.3	Recommended Operating Conditions.....	<b>4</b>	11.1	Layout Guidelines .....	<b>30</b>
6.4	Thermal Information .....	<b>4</b>	11.2	Layout Example .....	<b>31</b>
6.5	Electrical Characteristics.....	<b>5</b>	<b>12</b>	器件和文档支持 .....	<b>32</b>
6.6	Timing Requirements .....	<b>7</b>	12.1	器件支持 .....	<b>32</b>
6.7	Switching Characteristics .....	<b>7</b>	12.2	文档支持 .....	<b>32</b>
6.8	Typical Characteristics .....	<b>9</b>	12.3	接收文档更新通知 .....	<b>32</b>
<b>7</b>	<b>Parameter Measurement Information</b> .....	<b>14</b>	12.4	社区资源 .....	<b>32</b>
7.1	Digital Voltage Levels .....	<b>14</b>	12.5	商标 .....	<b>32</b>
<b>8</b>	<b>Detailed Description</b> .....	<b>15</b>	12.6	静电放电警告 .....	<b>32</b>
8.1	Overview .....	<b>15</b>	12.7	Glossary .....	<b>33</b>
8.2	Functional Block Diagram .....	<b>15</b>	<b>13</b>	机械、封装和可订购信息 .....	<b>34</b>
8.3	Feature Description.....	<b>16</b>			

## 4 修订历史记录

日期	修订版本	说明
2017 年 12 月	*	初始发行版

## 5 Pin Configuration and Functions



### Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	$\overline{\text{CS}}$	Digital input	Chip-select signal, active low
2	SDO	Digital output	Serial data out
3	SCLK	Digital input	Serial clock
4	DVDD	Supply	Digital I/O supply voltage
5	GND	Supply	Ground for power supply, all analog and digital signals are referred to this pin
6	AVDD	Supply	Analog power-supply input, also provides the reference voltage to the ADC
7	AINP	Analog input	Analog signal input, positive
8	AINM	Analog input	Analog signal input, negative

## 6 Specifications

### 6.1 Absolute Maximum Ratings<sup>(1)</sup>

	MIN	MAX	UNIT
AVDD to GND	-0.3	3.9	V
DVDD to GND	-0.3	3.9	V
AINP to GND	-0.3	AVDD + 0.3	V
AINM to GND	-0.3	AVDD + 0.3	V
Input current to any pin except supply pins	-10	10	mA
Digital input voltage to GND	-0.3	DVDD + 0.3	V
Storage temperature, T <sub>stg</sub>	-60	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000
		Charged device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
AVDD	Analog supply voltage range	2.35	3.3	3.6	V
DVDD	Digital supply voltage range	1.65	1.8	3.6	V
T <sub>A</sub>	Operating free-air temperature	-40	25	125	°C

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		ADS7057	UNIT
		RUG (X2QFN)	
		8 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	177.5	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	51.5	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	76.7	°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	1	°C/W
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	76.7	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

at  $V_{DD} = 3.3\text{ V}$ ,  $DV_{DD} = 1.65\text{ V to }3.6\text{ V}$ ,  $f_{\text{sample}} = 2.5\text{ MSPS}$ , and  $V_{\text{CM}} = 1.65\text{ V}$  (unless otherwise noted); minimum and maximum values for  $T_A = -40^\circ\text{C to }+125^\circ\text{C}$ ; typical values at  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>ANALOG INPUT</b>						
Full-scale input voltage span <sup>(1)</sup>		-AVDD		AVDD	V	
Absolute input voltage range	AINP to GND	-0.1		AVDD + 0.1	V	
	AINM to GND	-0.1		AVDD + 0.1		
Common-mode voltage	(AINP + AINM) / 2	(AVDD / 2) - 0.1		(AVDD / 2) + 0.1	V	
$C_S$	Sampling capacitance		16		pF	
<b>SYSTEM PERFORMANCE</b>						
Resolution			14		Bits	
NMC	No missing codes	14			Bits	
INL <sup>(2)</sup>	Integral nonlinearity	-3	±0.9	3	LSB <sup>(3)</sup>	
DNL	Differential nonlinearity	-0.99	±0.3	1	LSB	
$E_O$ <sup>(2)</sup>	Offset error	After calibration <sup>(4)</sup>		±1	6	LSB
$dV_{OS}/dT$	Offset error drift with temperature		1.75		ppm/°C	
$E_G$ <sup>(2)</sup>	Gain error	-0.1	±0.01	0.1	%FS	
	Gain error drift with temperature		0.5		ppm/°C	
<b>SAMPLING DYNAMICS</b>						
$t_{\text{CONV}}$	Conversion time		$18 \times t_{\text{SCLK}}$		ns	
$t_{\text{ACQ}}$	Acquisition time	95			ns	
$f_{\text{SAMPLE}}$	Maximum throughput rate	60-MHz SCLK, AVDD = 2.35 V to 3.6 V		2.5	MHz	
	Aperture delay		3		ns	
	Aperture jitter, RMS		12		ps	
<b>DYNAMIC CHARACTERISTICS</b>						
SNR	Signal-to-noise ratio <sup>(5)</sup>	AVDD = 3.3 V, $f_{\text{IN}} = 2\text{ kHz}$	76	79.6	dB	
		AVDD = 2.5 V, $f_{\text{IN}} = 2\text{ kHz}$		78.5		
THD	Total harmonic distortion <sup>(5)(6)</sup>	$f_{\text{IN}} = 2\text{ kHz}$		-92	dB	
		$f_{\text{IN}} = 500\text{ kHz}$		-90.4		
		$f_{\text{IN}} = 1000\text{ kHz}$		-90.3		
SINAD	Signal-to-noise and distortion <sup>(5)</sup>	$f_{\text{IN}} = 2\text{ kHz}$	76	79.3	dB	
		$f_{\text{IN}} = 500\text{ kHz}$		78.1		
		$f_{\text{IN}} = 1000\text{ kHz}$		77.1		
SFDR	Spurious-free dynamic range <sup>(5)</sup>	$f_{\text{IN}} = 2\text{ kHz}$		95	dB	
		$f_{\text{IN}} = 500\text{ kHz}$		93.4		
		$f_{\text{IN}} = 1000\text{ kHz}$		92.4		
$BW_{(\text{fp})}$	Full-power bandwidth	At -3 dB		200	MHz	

(1) Ideal input span; does not include gain or offset error.

(2) See [Figure 31](#), [Figure 29](#), and [Figure 30](#) for statistical distribution data for INL, offset error, and gain error.

(3) LSB means least significant bit.

(4) See the [OFFCAL State](#) section for details.

(5) All specifications expressed in decibels (dB) refer to the full-scale input (FSR) and are tested with an input signal 0.5 dB below full-scale, unless otherwise noted.

(6) Calculated on the first nine harmonics of the input frequency.

**Electrical Characteristics (continued)**

at AVDD = 3.3 V, DVDD = 1.65 V to 3.6 V,  $f_{\text{sample}} = 2.5$  MSPS, and  $V_{\text{CM}} = 1.65$  V (unless otherwise noted); minimum and maximum values for  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ ; typical values at  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>DIGITAL INPUT/OUTPUT (CMOS Logic Family)</b>						
$V_{\text{IH}}$	High-level input voltage <sup>(7)</sup>		0.65 DVDD	DVDD + 0.3	V	
$V_{\text{IL}}$	Low-level input voltage <sup>(7)</sup>		-0.3	0.35 DVDD	V	
$V_{\text{OH}}$	High-level output voltage <sup>(7)</sup>	At $I_{\text{source}} = 500 \mu\text{A}$	0.8 DVDD	DVDD	V	
		At $I_{\text{source}} = 2 \text{ mA}$	DVDD - 0.45	DVDD		
$V_{\text{OL}}$	Low-level output voltage <sup>(7)</sup>	At $I_{\text{sink}} = 500 \mu\text{A}$	0	0.2 DVDD	V	
		At $I_{\text{sink}} = 2 \text{ mA}$	0	0.45		
<b>POWER-SUPPLY REQUIREMENTS</b>						
AVDD	Analog supply voltage		2.35	3	3.6	V
DVDD	Digital I/O supply voltage		1.65	3	3.6	V
$I_{\text{AVDD}}$	Analog supply current	AVDD = 3.3 V, $f_{\text{SAMPLE}} = 2.5$ MSPS		1100	1400	$\mu\text{A}$
		AVDD = 3.3 V, $f_{\text{SAMPLE}} = 100$ kSPS		47	56	
		AVDD = 3.3 V, $f_{\text{SAMPLE}} = 10$ kSPS		5		
		AVDD = 2.5 V, $f_{\text{SAMPLE}} = 2.5$ MSPS		820		
		Static current with $\overline{\text{CS}}$ and SCLK high		0.02		
$I_{\text{DVDD}}$	Digital supply current	DVDD = 1.8 V, CS $\overline{\text{DO}} = 20$ pF, output code = 2AAAh <sup>(8)</sup>		630		$\mu\text{A}$
		DVDD = 1.8 V, static current with $\overline{\text{CS}}$ and SCLK high		0.01		

(7) Digital voltage levels comply with the JESD8-7A standard for DVDD from 1.65 V to 1.95 V; see the [Parameter Measurement Information](#) section for details.

(8) See the [Estimating Digital Power Consumption](#) section for details.

## 6.6 Timing Requirements

all specifications are at AVDD = 2.35 V to 3.6 V, DVDD = 1.65 V to 3.6 V, and C<sub>LOAD-SDO</sub> = 20 pF (unless otherwise noted); minimum and maximum values for T<sub>A</sub> = –40°C to +125°C; typical values at T<sub>A</sub> = 25°C

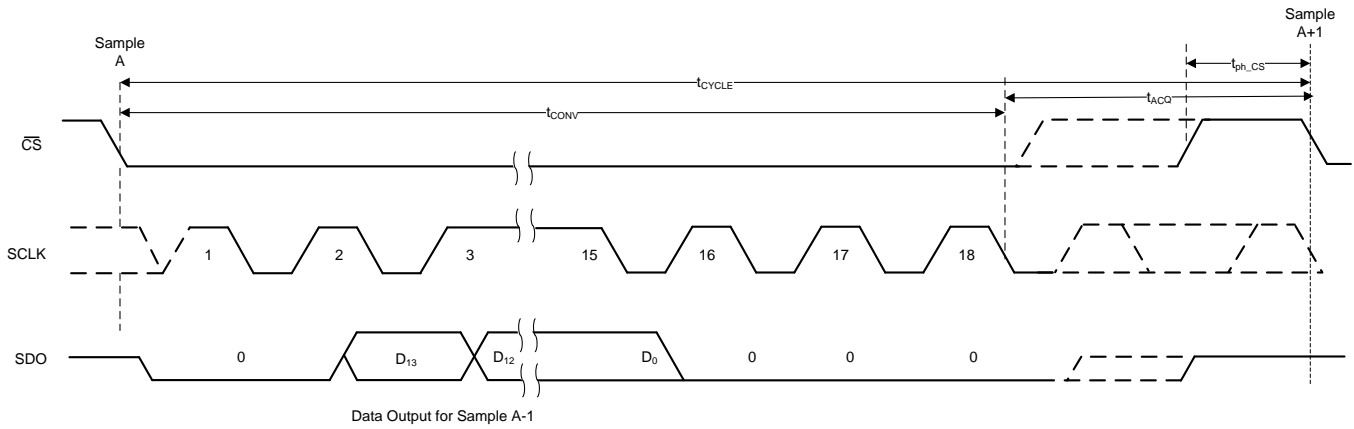
		MIN	TYP	MAX	UNIT
t <sub>CLK</sub>	Time period of SCLK	16.66			ns
t <sub>su_CSCK</sub>	Setup time: $\overline{CS}$ falling edge to SCLK falling edge	7			ns
t <sub>ht_CKCS</sub>	Hold time: SCLK rising edge to $\overline{CS}$ rising edge	8			ns
t <sub>ph_CK</sub>	SCLK high time	0.45		0.55	t <sub>SCLK</sub>
t <sub>pl_CK</sub>	SCLK low time	0.45		0.55	t <sub>SCLK</sub>
t <sub>ph_CS</sub>	$\overline{CS}$ high time	15			ns

## 6.7 Switching Characteristics

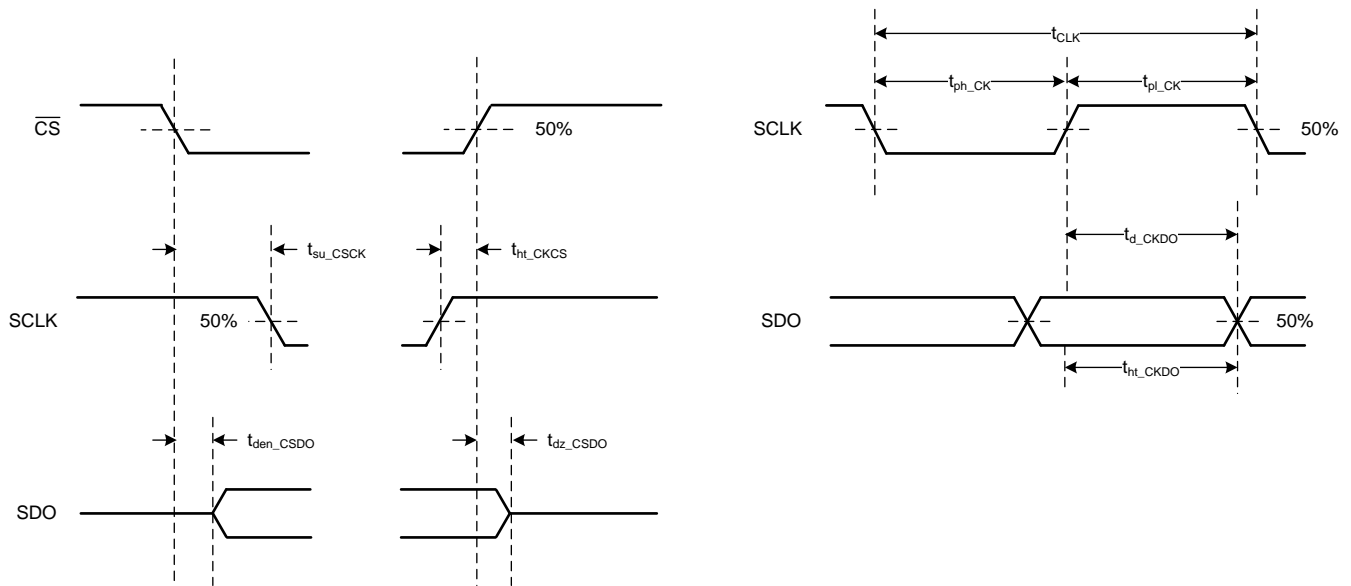
all specifications are at AVDD = 2.35 V to 3.6 V, DVDD = 1.65 V to 3.6 V, and C<sub>LOAD-SDO</sub> = 20 pF (unless otherwise noted); minimum and maximum values for T<sub>A</sub> = –40°C to +125°C; typical values at T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>CYCLE</sub> <sup>(1)</sup>	Cycle time	400			ns
t <sub>CONV</sub>	Conversion time		18 × t <sub>SCLK</sub>		ns
t <sub>den_CSDO</sub>	Delay time: $\overline{CS}$ falling edge to data enable			6.5	ns
t <sub>d_CKDO</sub>	Delay time: SCLK rising edge to (next) data valid on SDO			10	ns
t <sub>ht_CKDO</sub>	SCLK rising edge to current data invalid	2.5			ns
t <sub>dz_CSDO</sub>	Delay time: $\overline{CS}$ rising edge to SDO going to tri-state	5.5			ns

(1) t<sub>CYCLE</sub> = 1 / f<sub>SAMPLE</sub>.



**Figure 1. Serial Transfer Frame**

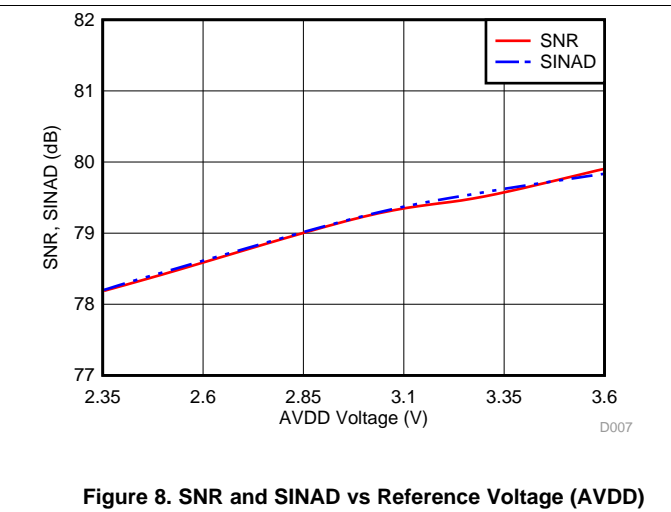
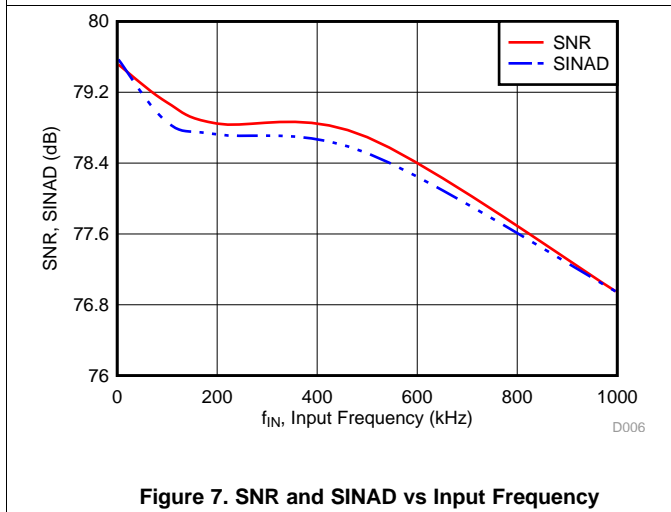
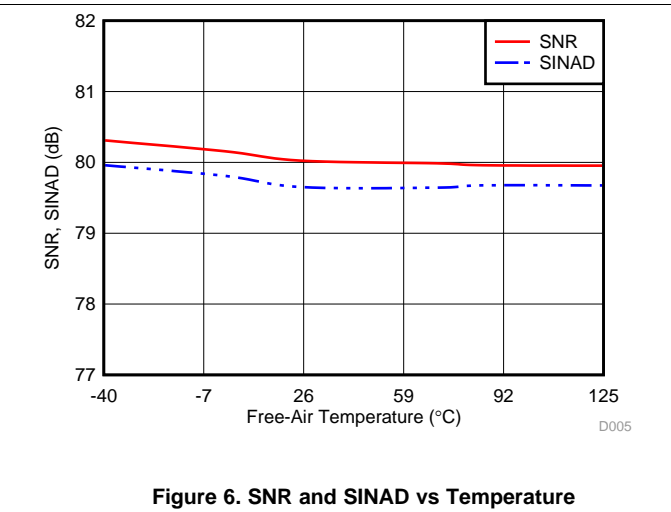
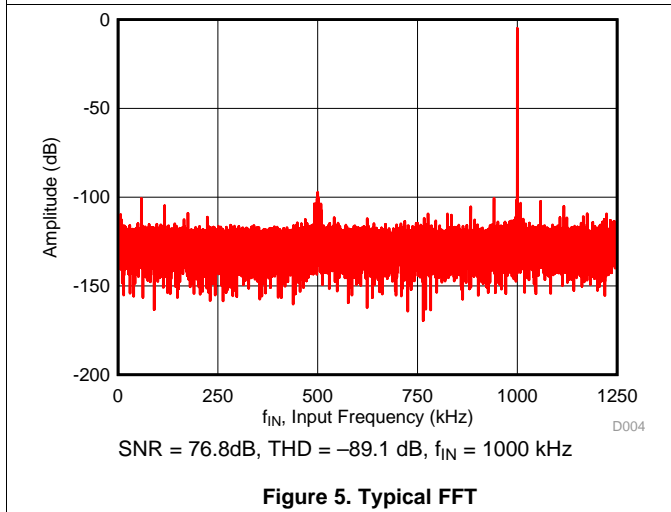
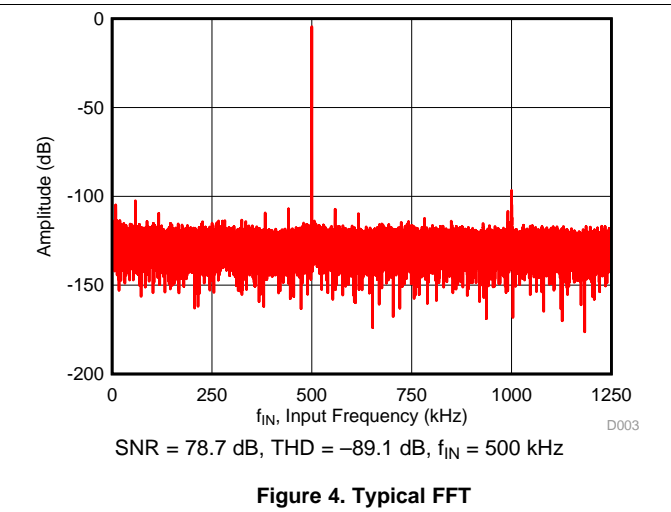
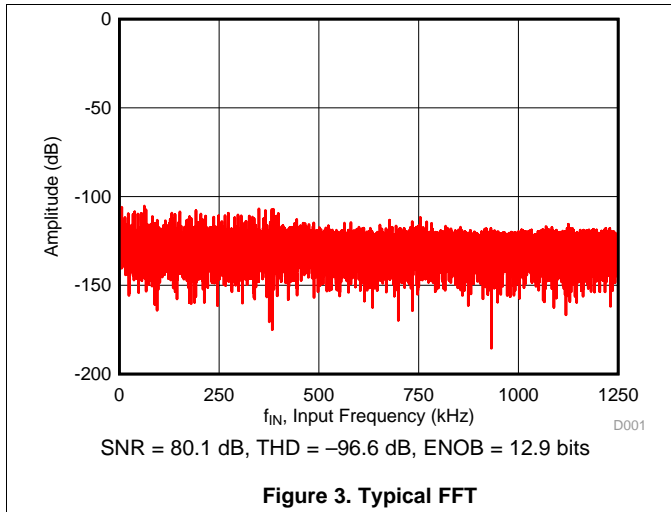


**Figure 2. Timing Specifications**



### 6.8 Typical Characteristics

at  $T_A = 25^\circ\text{C}$ ,  $AVDD = 3.3\text{ V}$ ,  $DVDD = 1.8\text{ V}$ ,  $f_{IN} = 2\text{ kHz}$ , and  $f_{\text{sample}} = 2.5\text{ MSPS}$  (unless otherwise noted)



Typical Characteristics (continued)

at  $T_A = 25^\circ\text{C}$ ,  $AVDD = 3.3\text{ V}$ ,  $DVDD = 1.8\text{ V}$ ,  $f_{IN} = 2\text{ kHz}$ , and  $f_{\text{sample}} = 2.5\text{ MSPS}$  (unless otherwise noted)

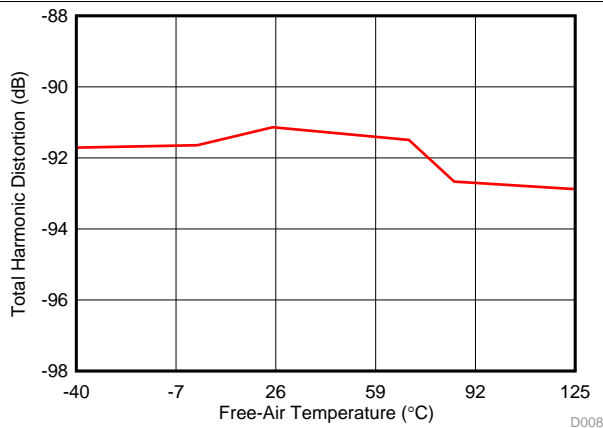


Figure 9. THD vs Temperature

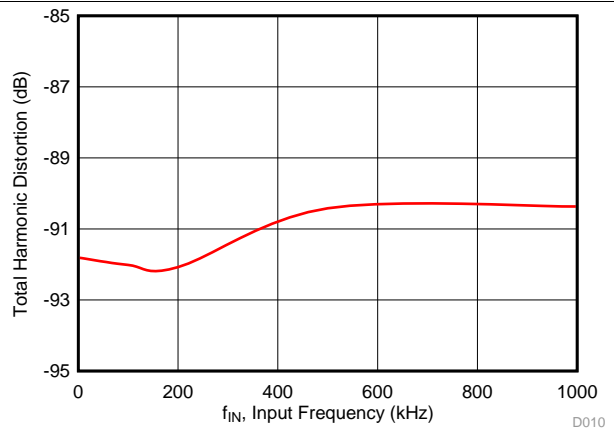


Figure 10. THD vs Input Frequency

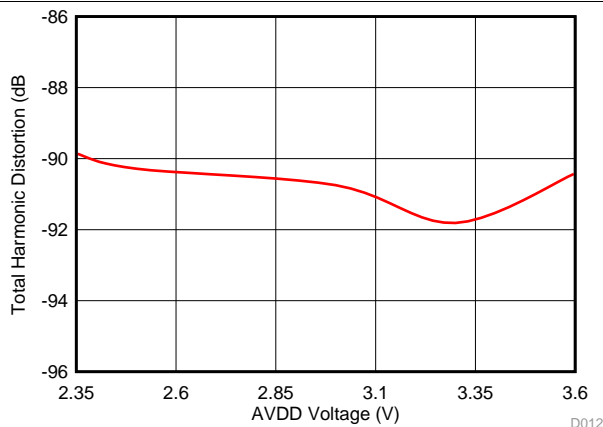


Figure 11. THD vs Reference Voltage (AVDD)

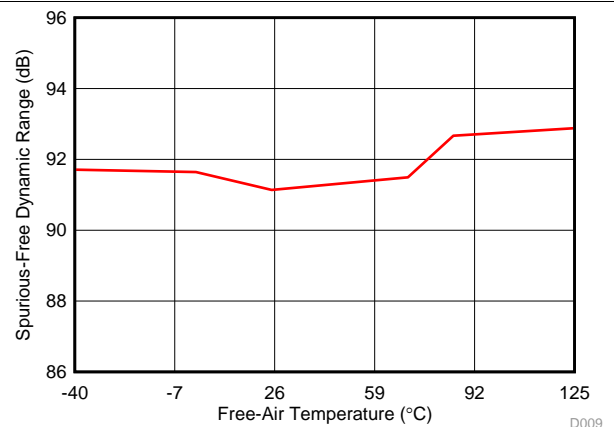


Figure 12. SFDR vs Temperature

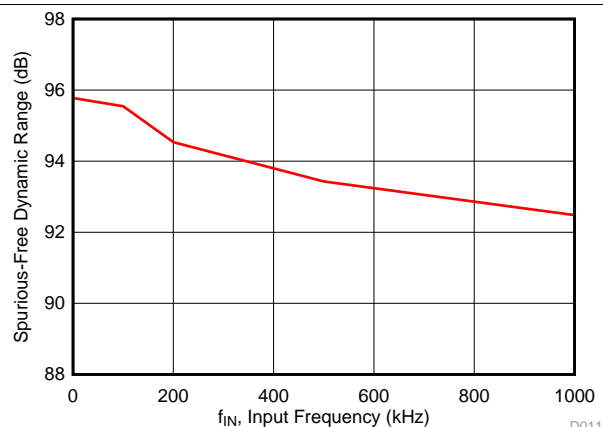


Figure 13. SFDR vs Input Frequency

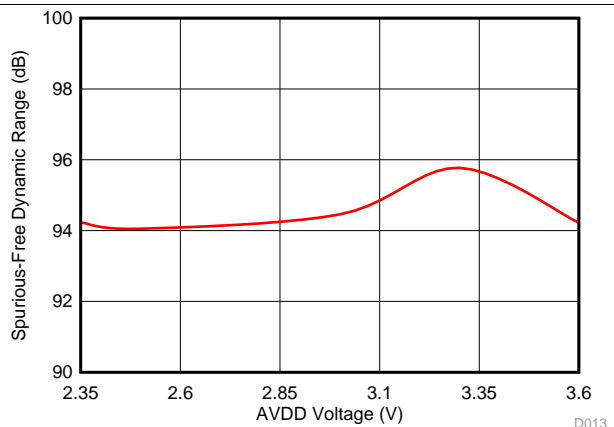


Figure 14. SFDR vs Reference Voltage (AVDD)

### Typical Characteristics (continued)

at  $T_A = 25^\circ\text{C}$ ,  $AVDD = 3.3\text{ V}$ ,  $DVDD = 1.8\text{ V}$ ,  $f_{IN} = 2\text{ kHz}$ , and  $f_{sample} = 2.5\text{ MSPS}$  (unless otherwise noted)

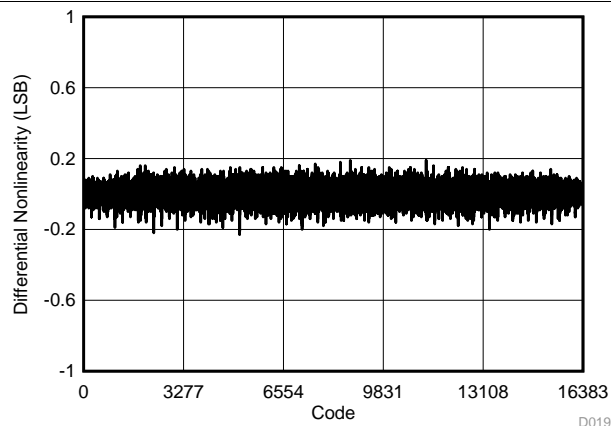


Figure 15. Typical DNL

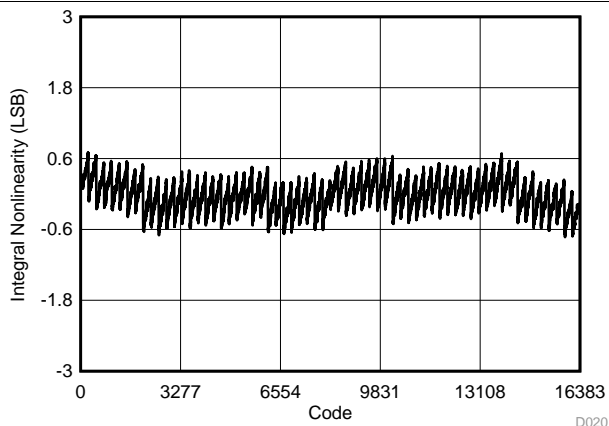


Figure 16. Typical INL

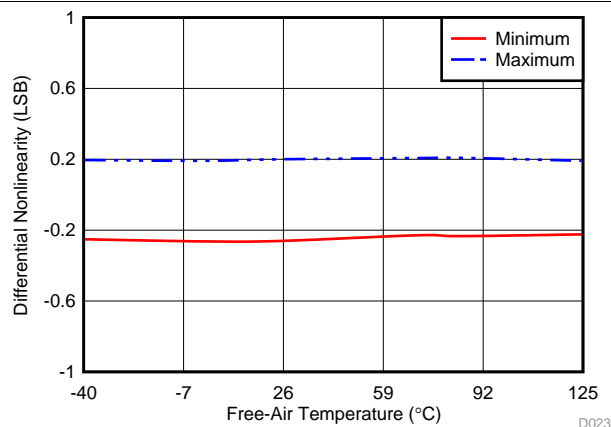


Figure 17. DNL vs Temperature

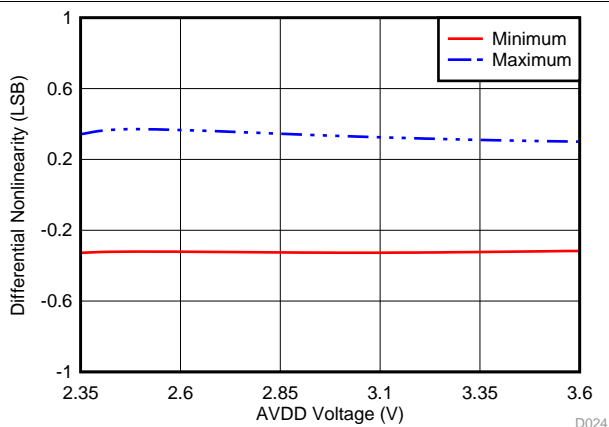


Figure 18. DNL vs Reference Voltage

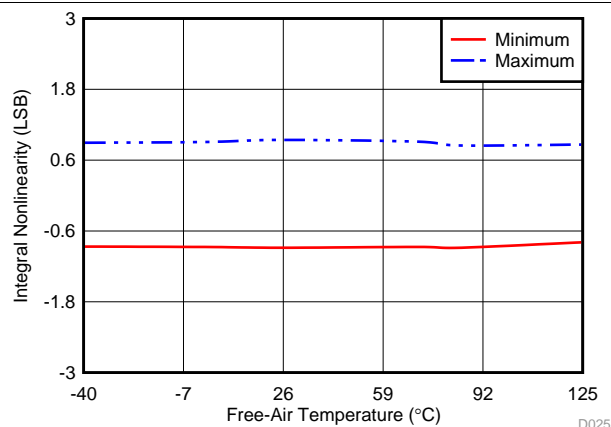


Figure 19. INL vs Temperature

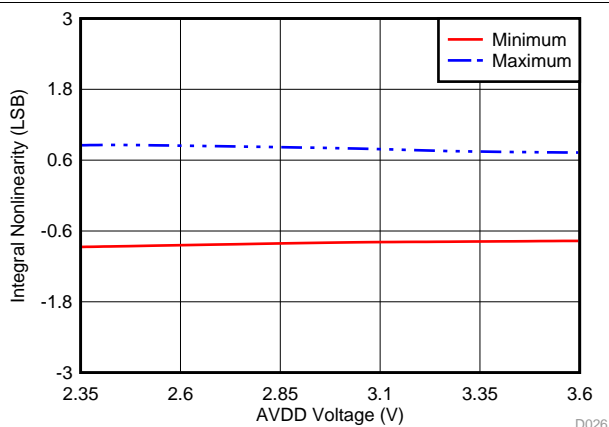


Figure 20. INL vs Reference Voltage

Typical Characteristics (continued)

at  $T_A = 25^\circ\text{C}$ ,  $AVDD = 3.3\text{ V}$ ,  $DVDD = 1.8\text{ V}$ ,  $f_{IN} = 2\text{ kHz}$ , and  $f_{sample} = 2.5\text{ MSPS}$  (unless otherwise noted)

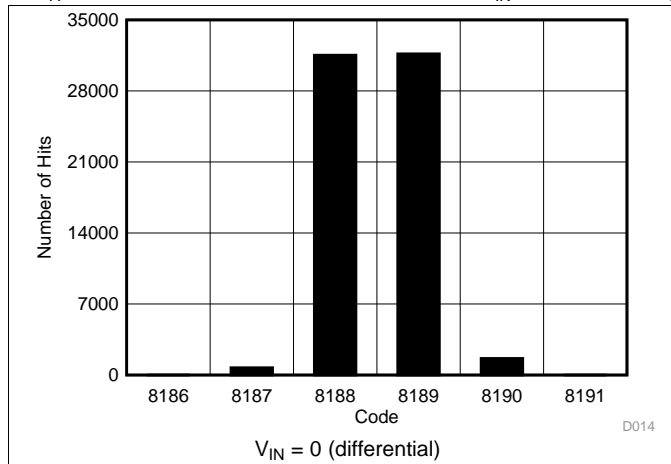


Figure 21. DC Input Histogram

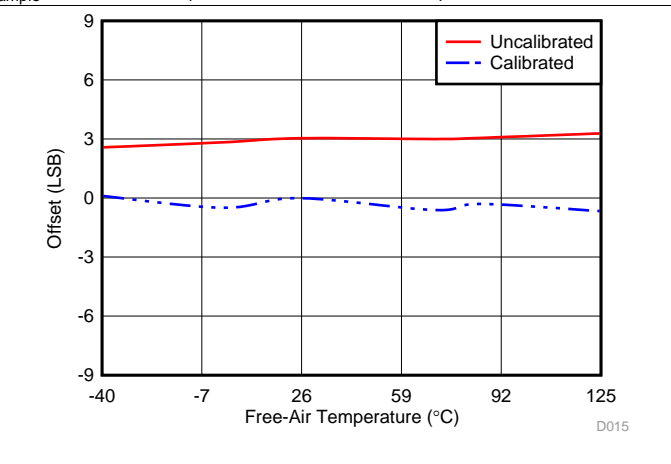


Figure 22. Offset vs Temperature

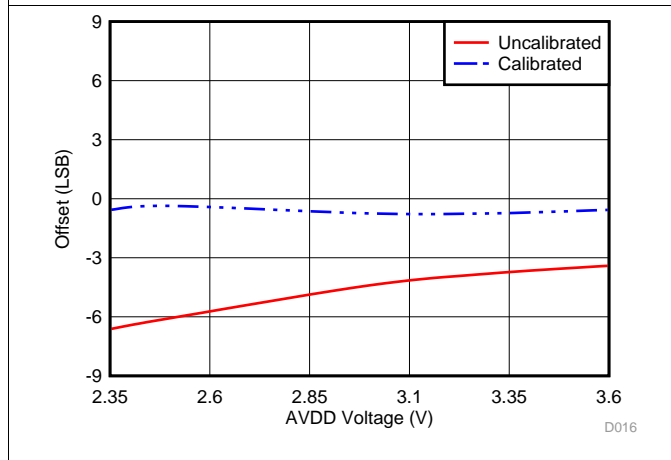


Figure 23. Offset vs Reference Voltage (AVDD)

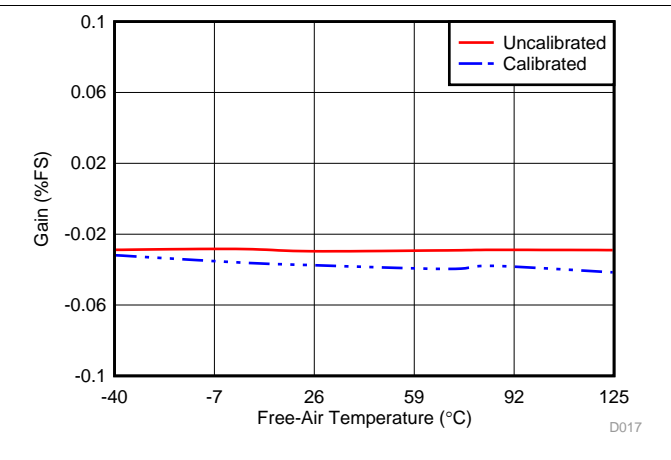


Figure 24. Gain Error vs Temperature

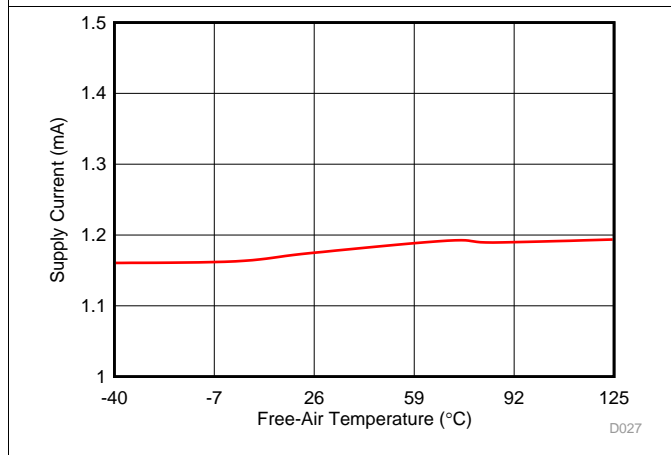


Figure 25. AVDD Current vs Temperature

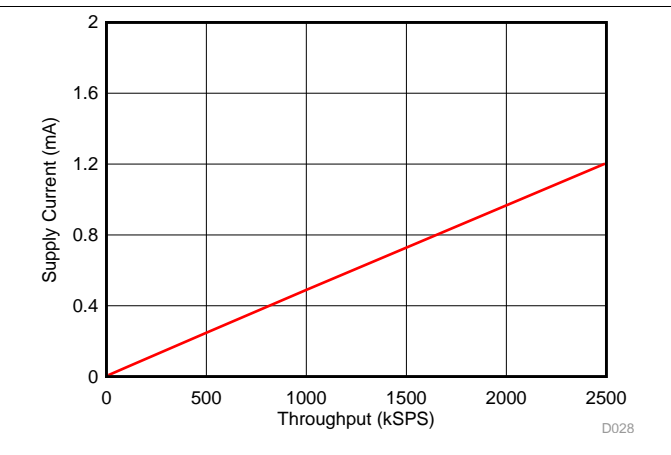


Figure 26. AVDD Current vs Throughput

Typical Characteristics (continued)

at  $T_A = 25^\circ\text{C}$ ,  $AVDD = 3.3\text{ V}$ ,  $DVDD = 1.8\text{ V}$ ,  $f_{IN} = 2\text{ kHz}$ , and  $f_{sample} = 2.5\text{ MSPS}$  (unless otherwise noted)

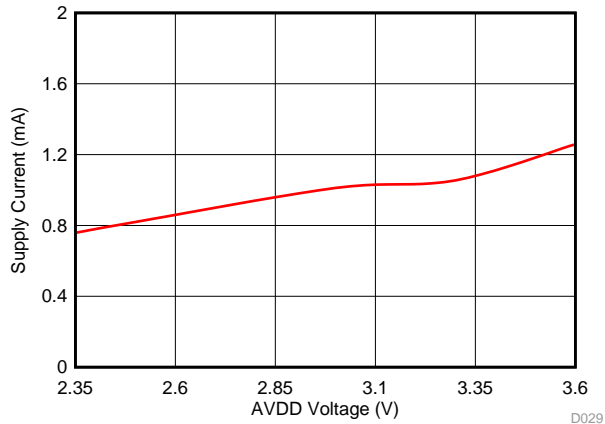


Figure 27. AVDD Current vs AVDD Voltage

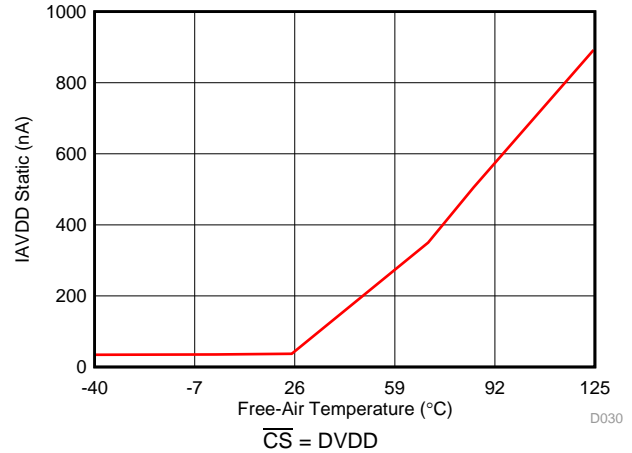


Figure 28. Static AVDD Current vs Temperature

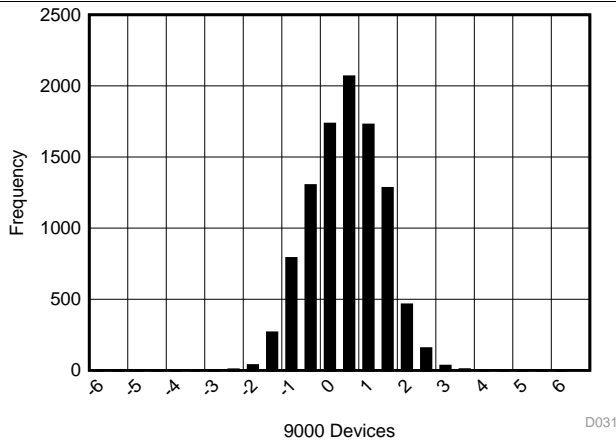


Figure 29. Typical Offset Error Distribution

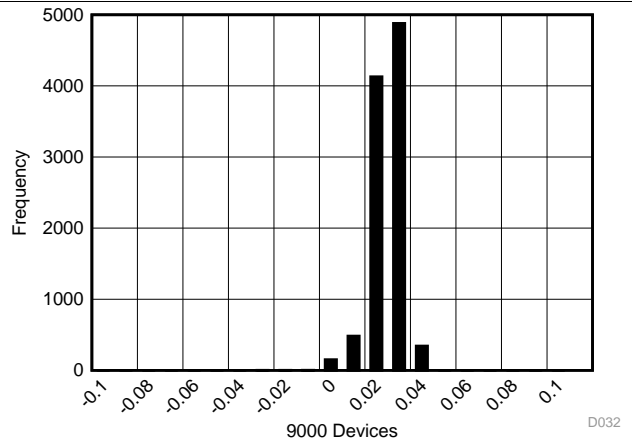


Figure 30. Typical Gain Error Distribution

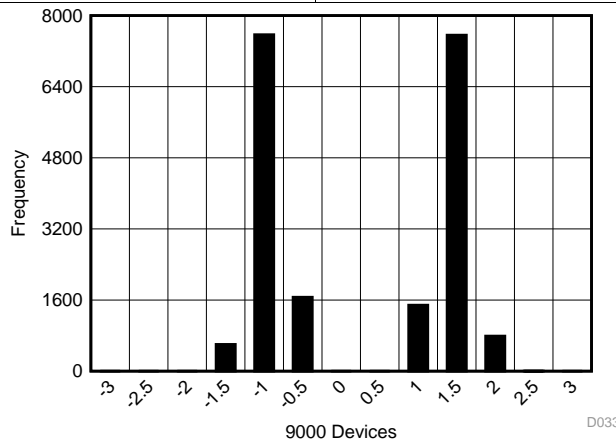


Figure 31. Typical INL Distribution

## 7 Parameter Measurement Information

### 7.1 Digital Voltage Levels

The device complies with the JESD8-7A standard for DVDD from 1.65 V to 1.95 V. Figure 32 shows voltage levels for the digital input and output pins.

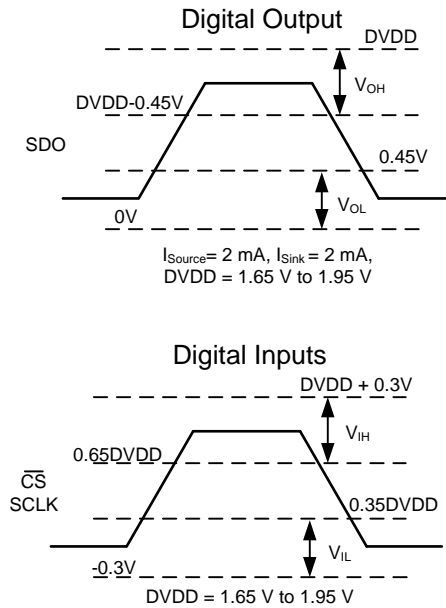


Figure 32. Digital Voltage Levels as per the JESD8-7A Standard

## 8 Detailed Description

### 8.1 Overview

The ADS7057 device belongs to a family of pin-to-pin compatible, high-speed, low-power, single-channel successive-approximation register (SAR) type analog-to-digital converters (ADCs). The device family includes multiple resolutions, throughputs, and analog input variants (see [Table 1](#) for a list of devices).

The ADS7057 is a 14-bit, 2.5-MSPS SAR ADC that supports fully-differential inputs in the range of  $\pm AVDD$ , for  $AVDD$  in the range of 2.35 V to 3.6 V (see the [Analog Input](#) section for details on the analog input pins).

The internal offset calibration feature (see the [OFFCAL State](#) section) maintains excellent offset specifications over the entire  $AVDD$  and temperature operating range.

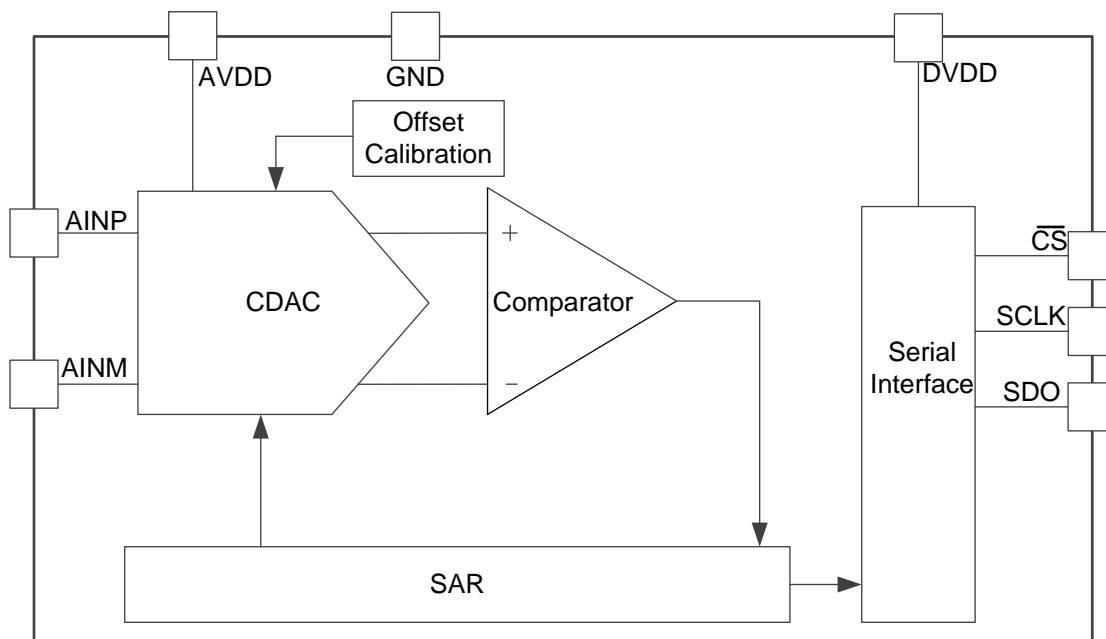
The device supports an SPI-compatible serial interface that is controlled by the  $\overline{CS}$  and SCLK signals. The input signal is sampled with the  $\overline{CS}$  falling edge and SCLK is used for both, conversion and serial data output (see the [Device Functional Modes](#) section, [Timing Requirements](#) table, and [Switching Characteristics](#) table).

The device supports a wide digital supply range (1.65 V to 3.6 V), enabling direct interfacing to a variety of host controllers. The ADS7057 complies with the JESD8-7A standard (see the [Digital Voltage Levels](#) section) for a normal DVDD range (1.65 V to 1.95 V).

The ADS7057 is available in an 8-pin, small, X2QFN package (see the [机械、封装和可订购信息](#) section for more details) and is specified over the extended industrial temperature range ( $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ ).

The small form-factor and extremely-low power consumption make this device suitable for space-constrained and battery-powered applications that require high-speed, high-resolution data acquisition (see the [Application Information](#) section).

### 8.2 Functional Block Diagram



## 8.3 Feature Description

### 8.3.1 Product Family

The devices listed in [Table 1](#) are all part of the same pin-to-pin compatible, high-speed, low-power, single-channel SAR ADC family. This device family includes multiple different ADC resolutions, throughputs, and analog input types to allow for greater flexibility in the end system. Devices in the same package are pin-compatible to offer a scalable family of devices for varying levels of end-system performance. The ADCs with device numbers ending in -Q1 are also AEC-Q100 qualified for automotive applications.

**Table 1. Device Family Comparison**

DEVICE NUMBER	RESOLUTION (Bits)	THROUGHPUT (MSPS)	INPUT TYPE	PACKAGES <sup>(1)</sup>
<a href="#">ADS7040</a>	8	1	Single-ended	X2QFN (8): 1.5 mm × 1.5 mm VSSOP (8): 2.0 mm × 3.1 mm
<a href="#">ADS7041</a>	10	1	Single-ended	X2QFN (8): 1.5 mm × 1.5 mm VSSOP (8): 2.0 mm × 3.1 mm
<a href="#">ADS7042</a>	12	1	Single-ended	X2QFN (8): 1.5 mm × 1.5 mm VSSOP (8): 2.0 mm × 3.1 mm
<a href="#">ADS7043</a>	12	1	Pseudo-differential	X2QFN (8): 1.5 mm × 1.5 mm VSSOP (8): 2.0 mm × 3.1 mm
<a href="#">ADS7044</a>	12	1	Fully-differential	X2QFN (8): 1.5 mm × 1.5 mm VSSOP (8): 2.0 mm × 3.1 mm
<a href="#">ADS7029-Q1</a>	8	2	Single-ended	VSSOP (8): 2.0 mm × 3.1 mm
<a href="#">ADS7039-Q1</a>	10	2	Single-ended	VSSOP (8): 2.0 mm × 3.1 mm
<a href="#">ADS7049-Q1</a>	12	2	Single-ended	VSSOP (8): 2.0 mm × 3.1 mm
<a href="#">ADS7046</a>	12	3	Single-ended	X2QFN (8): 1.5 mm × 1.5 mm
<a href="#">ADS7047</a>	12	3	Fully-differential	X2QFN (8): 1.5 mm × 1.5 mm
<a href="#">ADS7052</a>	14	1	Single-ended	X2QFN (8): 1.5 mm × 1.5 mm
<a href="#">ADS7054</a>	14	1	Fully-differential	X2QFN (8): 1.5 mm × 1.5 mm
<a href="#">ADS7056</a>	14	2.5	Single-ended	X2QFN (8): 1.5 mm × 1.5 mm
<a href="#">ADS7057</a>	14	2.5	Fully-differential	X2QFN (8): 1.5 mm × 1.5 mm

(1) Devices listed in the same package are pin-compatible.



### 8.3.2 Analog Input

The device supports a unipolar, fully-differential analog input signal. Figure 33 shows a small-signal equivalent circuit of the sample-and-hold circuit. The sampling switch is represented by a resistance ( $R_{S1}$  and  $R_{S2}$ , typically  $50\ \Omega$ ) in series with an ideal switch ( $SW_1$  and  $SW_2$ ). The sampling capacitors,  $C_{S1}$  and  $C_{S2}$ , are typically  $16\ \text{pF}$ .

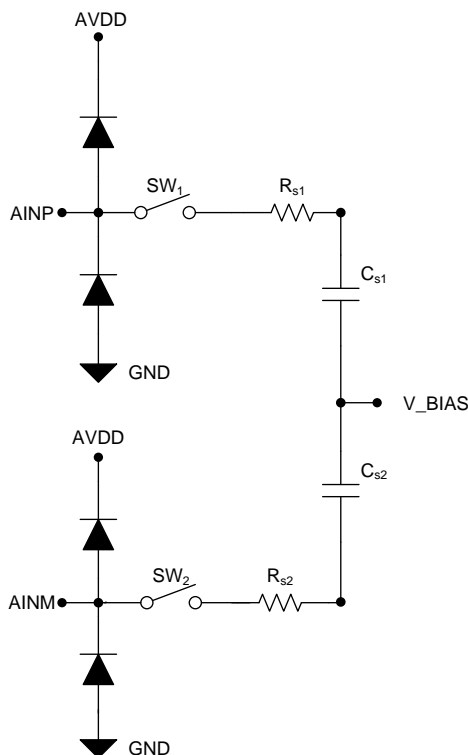


Figure 33. Equivalent Input Circuit for the Sampling Stage

During the acquisition process, both positive and negative inputs are individually sampled on  $C_{S1}$  and  $C_{S2}$ , respectively. During the conversion process, the device converts for the voltage difference between the two sampled values:  $V_{AINP} - V_{AINM}$ .

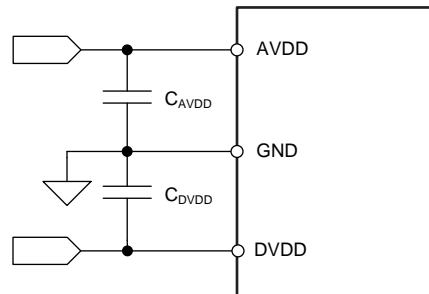
Each analog input pin has electrostatic discharge (ESD) protection diodes to AVDD and GND. Keep the analog inputs within the specified range to avoid turning the diodes on.

The full-scale analog input range (FSR) is  $V_{FSR} = -AVDD$  to  $AVDD$  and the common-mode input voltage is  $AVDD / 2 \pm 0.1\ \text{V}$ .

### 8.3.3 Reference

The device uses the analog supply voltage (AVDD) as the reference voltage for the analog to digital conversion. During the conversion process, the internal capacitors are switched to the AVDD pin as per the successive approximation algorithm. A voltage reference must be selected with low temperature drift, high output current drive and low output impedance. TI recommends a 3.3- $\mu\text{F}$  ( $C_{\text{AVDD}}$ ), low equivalent series resistance (ESR) ceramic capacitor between the AVDD and GND pins. This decoupling capacitor provides the instantaneous charge required by the internal circuit during the conversion process and maintains a stable dc voltage on the AVDD pin.

See the [Power Supply Recommendations](#) and [Layout Example](#) sections for component recommendations and layout guidelines.



**Figure 34. Reference for the Device**

### 8.3.4 ADC Transfer Function

The device supports a unipolar fully-differential analog input signal. The output is in two's complement format. Figure 35 and Table 2 show the ideal transfer characteristics for the device.

The least significant bit for the device is given by:

$$1 \text{ LSB} = 2 \times V_{\text{REF}} / 2^N$$

where:

- $V_{\text{REF}}$  = Voltage applied between the AVDD and GND pins
- $N = 14$

(1)

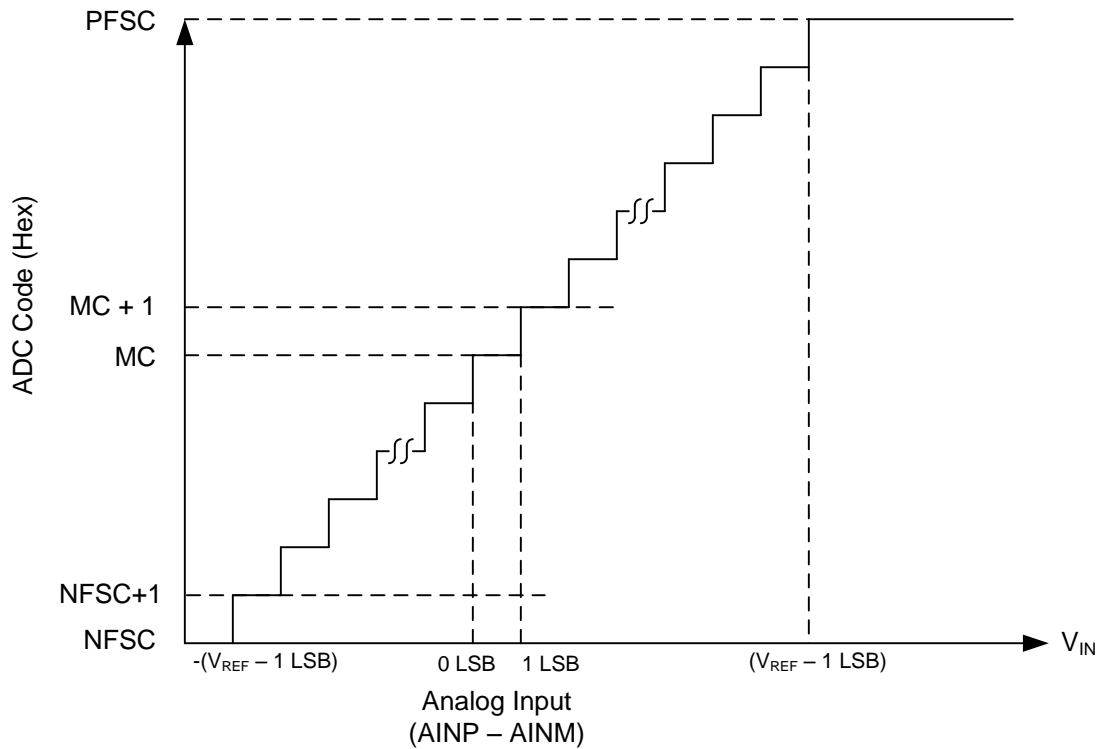


Figure 35. Ideal Transfer Characteristics

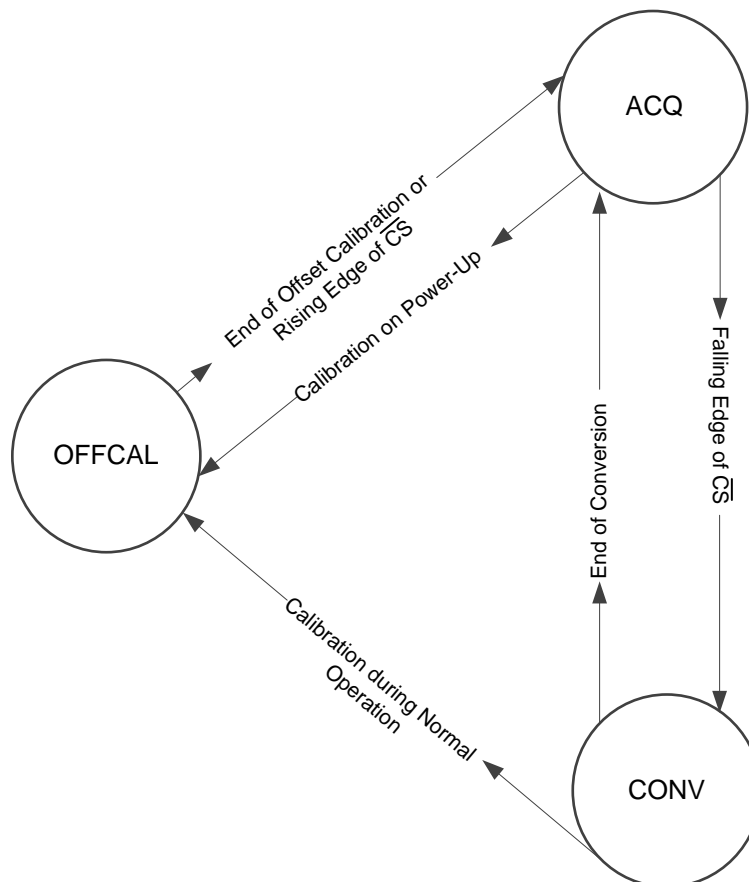
Table 2. Transfer Characteristics

INPUT VOLTAGE (AINP – AINM)	CODE	DESCRIPTION	IDEAL OUTPUT CODE (Hex)
$\leq -(V_{\text{REF}} - 1 \text{ LSB})$	NFSC	Negative full-scale code	2000
$-(V_{\text{REF}} - 1 \text{ LSB})$ to $-(V_{\text{REF}} - 2 \text{ LSB})$	NFSC + 1	—	2001
0 LSB to 1 LSB	MC	Mid code	0000
1 LSB to 2 LSB	MC + 1	—	0001
$\geq V_{\text{REF}} - 1 \text{ LSB}$	PFSC	Positive full-scale code	1FFF

## 8.4 Device Functional Modes

The device supports a simple, SPI-compatible interface to the external host. On power-up, the device is in the ACQ state. The  $\overline{CS}$  signal defines one conversion and serial data transfer frame. A frame starts with a  $\overline{CS}$  falling edge and ends with a  $\overline{CS}$  rising edge. The SDO pin is tri-stated when  $\overline{CS}$  is high. With  $\overline{CS}$  low, the clock provided on the SCLK pin is used for conversion and data transfer. Output data are available on the SDO pin.

As shown in Figure 36, the device supports three functional states: acquisition (ACQ), conversion (CNV), and offset calibration (OFFCAL). The device status depends on the  $\overline{CS}$  and SCLK signals provided by the host controller.



**Figure 36. Functional State Diagram**

### 8.4.1 ACQ State

In the ACQ state, switches  $SW_1$  and  $SW_2$  connected to the analog input pins close and the device acquires the analog input signal on  $C_{S1}$  and  $C_{S2}$ . The device enters ACQ state at power-up, at the end of every conversion, and after completing the offset calibration. A  $\overline{CS}$  falling edge takes the device from the ACQ state to the CNV state.

The device consumes extremely low power from the AVDD and DVDD power supplies when in ACQ state.

## Device Functional Modes (continued)

### 8.4.2 CNV State

In the CNV state, the device uses the external clock to convert the sampled analog input signal to an equivalent digital code as per the transfer function illustrated in Figure 35. The conversion process requires a minimum of 18 SCLK falling edges to be provided within the frame. After the end of conversion process, the device automatically moves from the CNV state to the ACQ state. For acquisition of the next sample, a minimum time of  $t_{ACQ}$  must be provided.

Figure 37 shows a detailed timing diagram for the serial interface. In the first serial transfer frame after power-up, the device provides the first data as all zeros. In any frame, the clocks provided on the SCLK pin are also used to transfer the output data for the previous conversion. A leading 0 is output on the SDO pin on the  $\overline{CS}$  falling edge. The most significant bit (MSB) of the output data is launched on the SDO pin on the rising edge after the first SCLK falling edge. Subsequent output bits are launched on the subsequent rising edges provided on SCLK. When all 14 output bits are shifted out, the device outputs 0's on the subsequent SCLK rising edges. The device enters the ACQ state after 18 clocks and a minimum time of  $t_{ACQ}$  must be provided for acquiring the next sample. If the device is provided with less than 18 SCLK falling edges in the present serial transfer frame, the device provides an invalid conversion result in the next serial transfer frame.

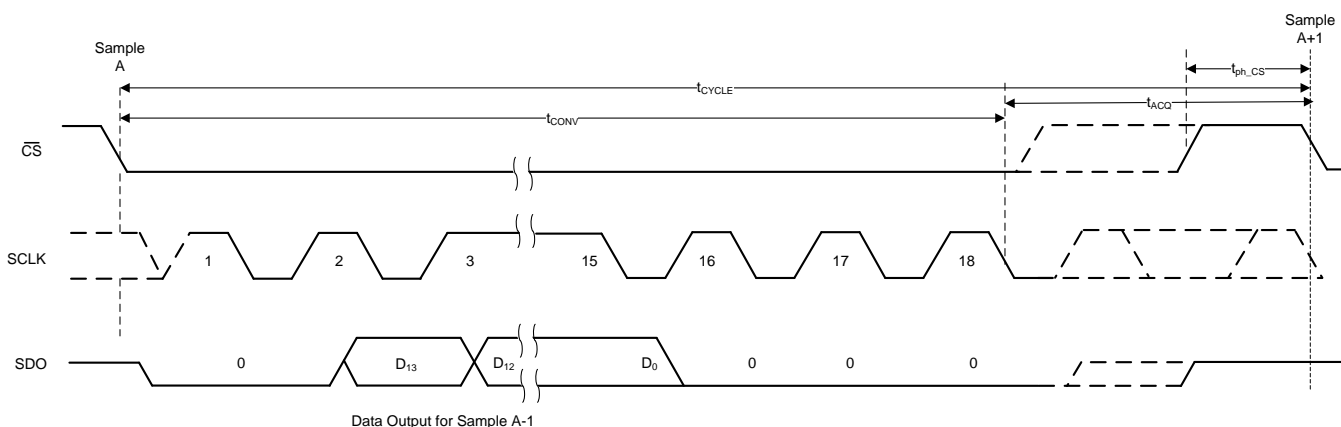


Figure 37. Serial Interface Timing Diagram

## Device Functional Modes (continued)

### 8.4.3 OFFCAL State

In the offset calibration (OFFCAL) state, the sampling capacitors are disconnected from the analog input pins (AINP and AINM) and the device calibrates and corrects for any internal offset errors. The offset calibration is effective for all subsequent conversions until the device is powered off. An offset calibration cycle is recommended at power-up and whenever there is a significant change in the operating conditions for the device (such as in the AVDD voltage and operating temperature).

The host controller must provide a serial transfer frame as described in [Figure 38](#) or in [Figure 39](#) to enter the OFFCAL state.

#### 8.4.3.1 Offset Calibration on Power-Up

On power-up, the host must provide 24 SCLKs in the first serial transfer to enter the OFFCAL state. The device provides 0's on SDO during offset calibration. For acquisition of the next sample, a minimum time of  $t_{ACQ}$  must be provided.

If the host controller starts the offset calibration process but then pulls the  $\overline{CS}$  pin high before providing 24 SCLKs, then the offset calibration process is aborted and the device enters the ACQ state. [Figure 38](#) and [Table 3](#) provide the timing for offset calibration on power-up.

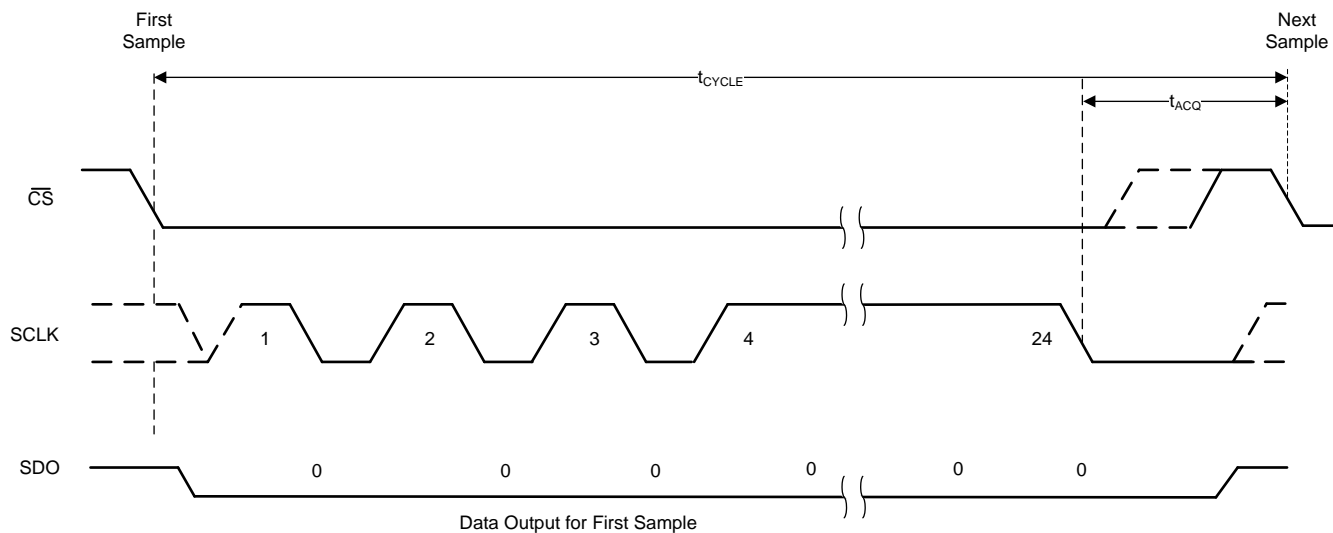


Figure 38. Timing for Offset Calibration on Power-Up

Table 3. Timing Specifications for Offset Calibration on Power-Up<sup>(1)</sup>

		MIN	TYP	MAX	UNIT
$t_{cycle}$	Cycle time for offset calibration on power-up	$24 \times t_{CLK} + t_{ACQ}$			ns
$t_{ACQ}$	Acquisition time	95			ns
$f_{SCLK}$	Frequency of SCLK	60			MHz

(1) In addition to the timing specifications of [Figure 38](#) and [Table 3](#), the timing specifications described in [Figure 2](#) and the [Timing Requirements](#) table are also applicable for offset calibration on power-up.

### 8.4.3.2 Offset Calibration During Normal Operation

During normal operation, the host must provide 64 SCLKs in the serial transfer frame to enter the OFFCAL state. The device provides the conversion result for the previous sample during the first 18 SCLKs and 0's on SDO for the rest of the SCLKs in the serial transfer frame. For acquisition of the next sample, a minimum time of  $t_{ACQ}$  must be provided.

If the host controller provides more than 18 SCLKs but pulls the  $\overline{CS}$  high before providing 64 SCLKs, then the offset calibration process is aborted and the device enters the ACQ state. Figure 39 and Table 4 provide the timing for offset calibration during normal operation.

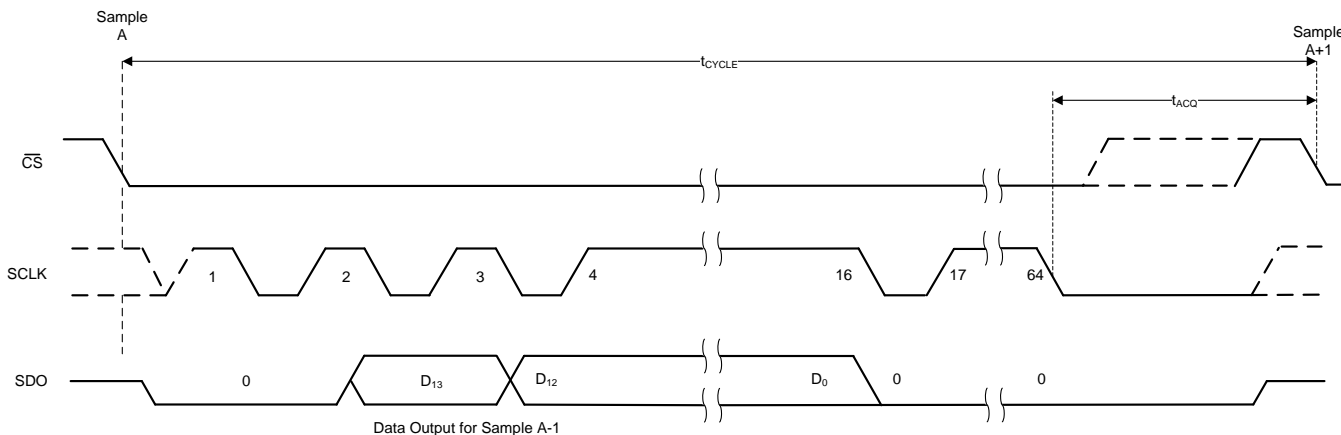


Figure 39. Timing for Offset Calibration During Normal Operation

Table 4. Timing Specifications for Offset Calibration During Normal Operation<sup>(1)</sup>

		MIN	TYP	MAX	UNIT
$t_{cycle}$	Cycle time for offset calibration on power-up	$64 \times t_{CLK} + t_{ACQ}$			ns
$t_{ACQ}$	Acquisition time	95			ns
$f_{SCLK}$	Frequency of SCLK	60			MHz

(1) In addition to the timing specifications of Figure 39 and Table 4, the timing specifications described in Figure 2 and the [Timing Requirements](#) table are also applicable for offset calibration during normal operation.

## 9 Application and Implementation

### NOTE

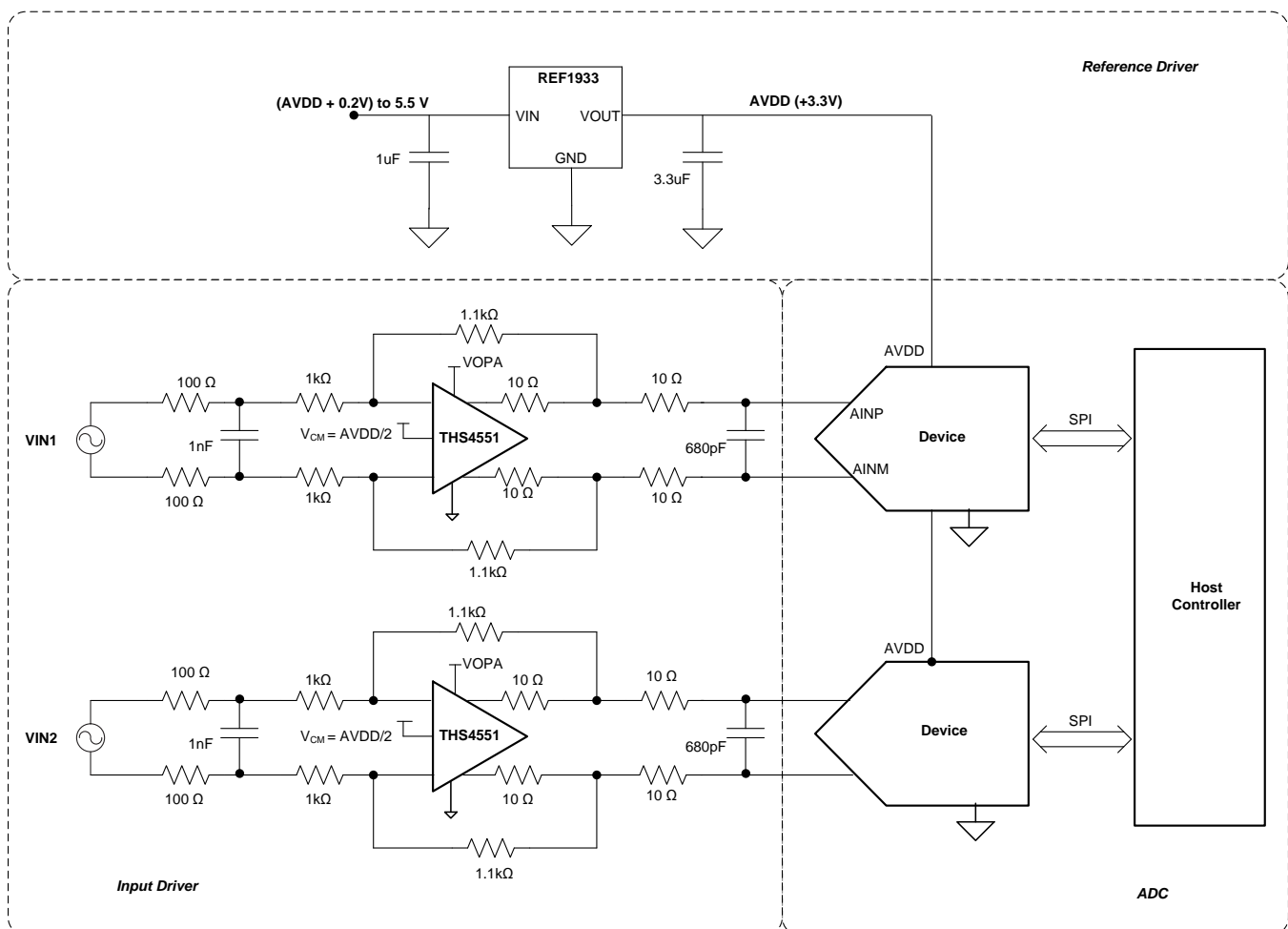
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The two primary supporting circuits required to maximize the performance of a high-precision, successive approximation register (SAR) analog-to-digital converter (ADC) are the input driver and the reference driver circuits. This section details some general principles for designing the input driver circuit, reference driver circuit, and provides typical application circuits designed for the device.

### 9.2 Typical Applications

#### 9.2.1 2-Channel, Simultaneous Sampling Data Acquisition Using the ADS7057



**Figure 40. 2-Channel, Simultaneous-Sampling Data Acquisition (DAQ) Circuit Using the ADS7057**



## Typical Applications (continued)

### 9.2.1.1 Design Requirements

The goal of the circuit shown in Figure 40 is to design a two-channel, simultaneous-sampling data acquisition (DAQ) circuit based on the ADS7057 with an SNR greater than 79 dB and a THD less than  $-85$  dB for input frequencies from 2 kHz to 50 kHz at a throughput of 2.5 MSPS. This simultaneous-sampling scheme is typically used in motor sine and cosine (sin-cos) encoders, resolvers, fish finders, sonar, and I-Q demodulation.

### 9.2.1.2 Detailed Design Procedure

The input driver circuit for a high-precision ADC mainly consists of two parts: a driving amplifier and charge kickback filter. Careful design of the front-end circuit is critical to meet the linearity and noise performance of a high-precision ADC.

#### 9.2.1.2.1 Low Distortion Charge Kickback Filter Design

Figure 41 shows the input circuit of a typical SAR ADC. During the acquisition phase, the SW switch closes and connects the sampling capacitor ( $C_{SH}$ ) to the input driver circuit. This action introduces a transient on the input pins of the SAR ADC. An ideal amplifier with  $0 \Omega$  of output impedance and infinite current drive can settle this transient in zero time. For a real amplifier with non-zero output impedance and finite drive strength, this switched capacitor load can create stability issues.

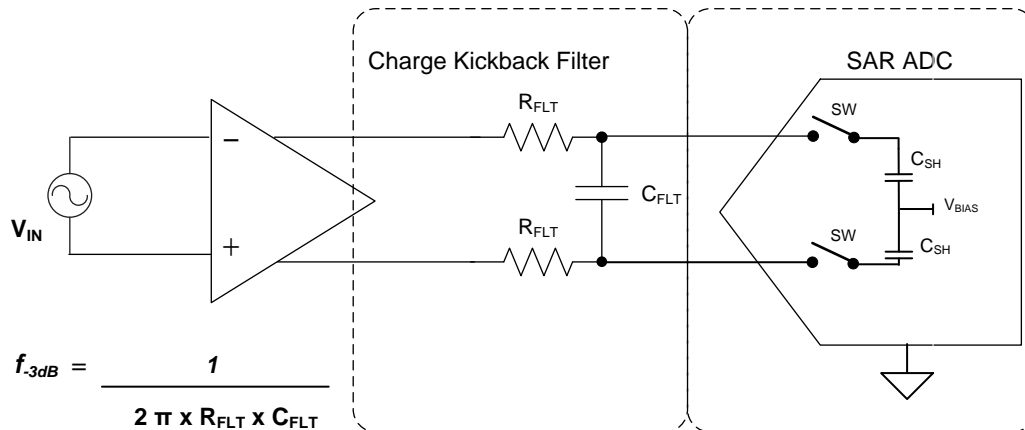


Figure 41. Input Sample-and-Hold Circuit for a Typical SAR ADC

For ac signals, the filter bandwidth must be kept low to band-limit the noise fed into the ADC input, thereby increasing the signal-to-noise ratio (SNR) of the system. Besides filtering the noise from the front-end drive circuitry, the RC filter also helps attenuate the sampling charge injection from the switched-capacitor input stage of the ADC. A filter capacitor,  $C_{FLT}$ , is connected across the ADC inputs. This capacitor helps reduce the sampling charge injection and provides a charge bucket to quickly charge the internal sample-and-hold capacitors during the acquisition process. As a rule of thumb, the value of this capacitor is at least 20 times the specified value of the ADC sampling capacitance. For this device, the input sampling capacitance is equal to 16 pF. Thus, the value of  $C_{FLT}$  is greater than 320 pF. Select a COG- or NPO-type capacitor because these capacitor types have a high-Q, low-temperature coefficient, and stable electrical characteristics under varying voltages, frequency, and time.

Driving capacitive loads can degrade the phase margin of the input amplifiers, thus making the amplifier marginally unstable. To avoid amplifier stability issues, series isolation resistors ( $R_{FLT}$ ) are used at the output of the amplifiers. A higher value of  $R_{FLT}$  is helpful from the amplifier stability perspective, but adds distortion as a result of interactions with the nonlinear input impedance of the ADC. Distortion increases with source impedance, input signal frequency, and input signal amplitude. Therefore, the selection of  $R_{FLT}$  requires balancing the stability and distortion of the design.

## Typical Applications (continued)

### 9.2.1.2.2 Input Amplifier Selection

The input amplifier bandwidth is typically much higher than the cutoff frequency of the charge kickback filter. Thus, TI strongly recommends performing a SPICE simulation to confirm that the amplifier has more than 40° phase margin with the selected filter. Simulation is critical because even with high-bandwidth amplifiers, some amplifiers can require more bandwidth than others to drive similar filters. To learn more about the SAR ADC input driver design, see the [TI Precision Labs training video series](#).

The [THS4551](#) is selected for its high bandwidth (135 MHz), low total harmonic distortion of -90 dBc at 100 kHz, and ultra-low noise of (3.2 nV/√Hz). The THS4551 is powered up from the power supply (VDD = 5 V and VSS = GND).

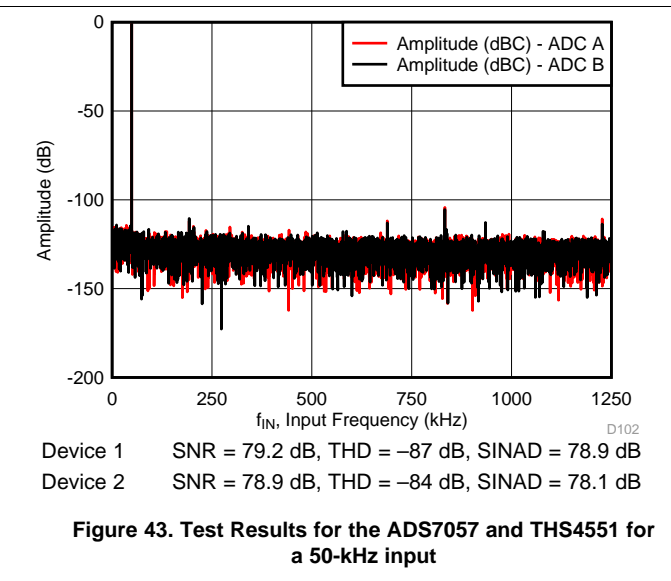
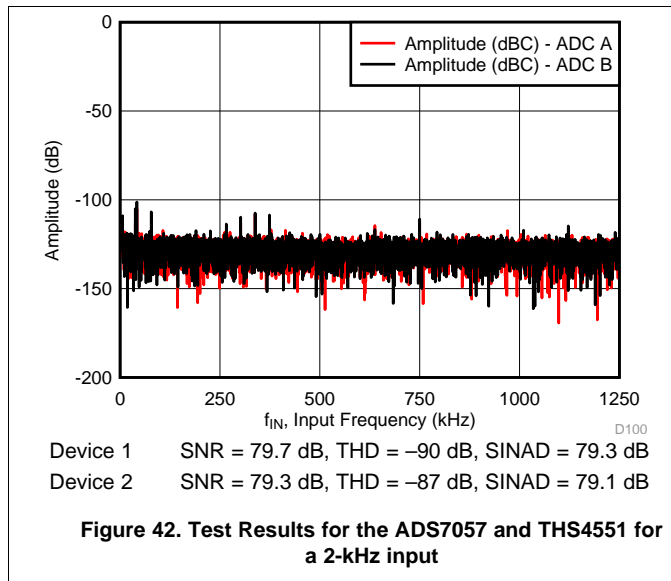
### 9.2.1.2.3 Reference Circuit

The ADS70xx uses the analog supply voltage (AVDD) as the reference voltage for the analog-to-digital conversion. During the conversion process, the internal capacitors are switched to the level of the AVDD pin as per the successive approximation algorithm. A voltage reference must be selected with low temperature drift, high output current drive, and low output impedance. For this application, the [REF1933](#) was selected as the voltage reference and analog power supply for the ADC. The [REF1933](#) has excellent temperature drift performance (25 ppm/°C), good initial accuracy (0.1%), high output drive capability (25 mA), and low quiescent current (360 μA). The [REF1933](#) also provides a bias voltage output of half the reference voltage ( $V_{REF} / 2$ ) that can be used as the common-mode input for the amplifier.

TI recommends a 3.3-μF ( $C_{AVDD}$ ), low equivalent series resistance (ESR) ceramic capacitor between the AVDD and GND pins. This decoupling capacitor provides the instantaneous charge required by the internal circuit during the conversion process and maintains a stable dc voltage on the AVDD pin.

### 9.2.1.3 Application Curves

[Figure 42](#) and [Figure 43](#) provide the measurement results for the circuit described in [Figure 40](#).



## Typical Applications (continued)

### 9.2.2 Improving Precision of Single-Ended Signal Source Measurements Using the ADS7057

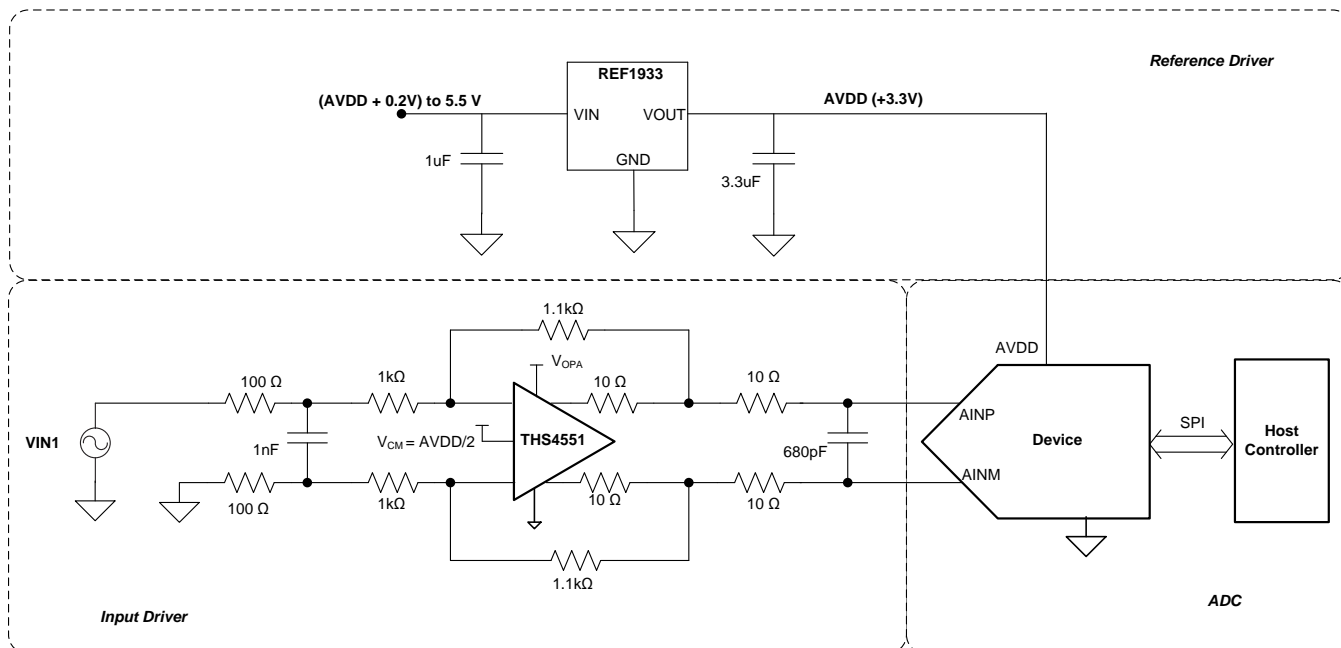


Figure 44. Interfacing Single-Ended Signals with the ADS7057 Using a Single-Ended to Differential Front-End

#### 9.2.2.1 Design Requirements

Some applications have sensor or signal inputs that are single ended. In order to increase the dynamic range, linearity, and precision of the system, such single-ended signals are often required to be interfaced with a differential input ADC. The goal of the design shown in Figure 44 is to interface a single-ended input source with the ADS7057 using a single-ended to differential front-end amplifier to achieve an SNR greater than 79 dB and a THD less than  $-85$  dB for input frequencies up to 10 kHz at a throughput of 2.5 MSPS.

#### 9.2.2.2 Detailed Design Procedure

To achieve a SNR greater than 79 dB, the operational amplifier must have high bandwidth in order to settle the input signal within the acquisition time of the ADC. The operational amplifier must have low noise to keep the total system noise below 20% of the input-referred noise of the ADC. For the application circuit shown in Figure 44, the THS4551 is selected for its high bandwidth (135 MHz), low total harmonic distortion of  $-90$  dBc at 100 kHz, and ultra-low noise of (3.2 nV/ $\sqrt{\text{Hz}}$ ). The THS4551 is powered up from the power supply (VDD = 5 V and VSS = GND).

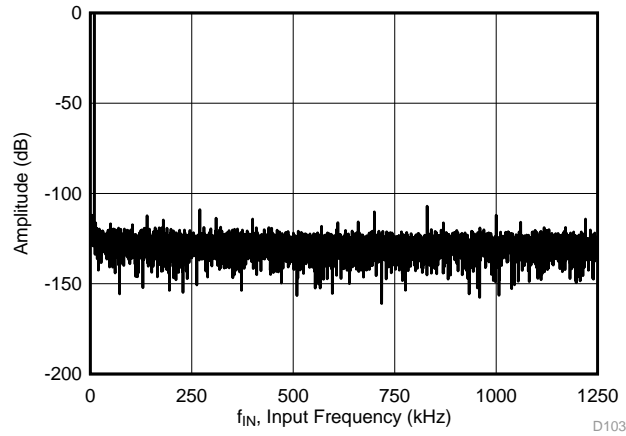
The THS4551 can be used in a single-ended to differential configuration as shown in Figure 44 without any performance degradation. This configuration enables single-ended input signals to be interfaced with differential input SAR ADCs (such as the ADS7057) to achieve higher system-level precision.

For this application, the REF1933 was selected as the voltage reference and analog power supply for the ADC. The REF1933 has excellent temperature drift performance (25 ppm/ $^{\circ}\text{C}$ ), good initial accuracy (0.1%), high output drive capability (25 mA), and low quiescent current (360  $\mu\text{A}$ ). The REF1933 also provides a bias voltage output of half the reference voltage ( $V_{\text{REF}} / 2$ ) that can be used as the common-mode input for the amplifier.

**Typical Applications (continued)**

**9.2.2.3 Application Curve**

Figure 45 shows the FFT plot for the ADS7057 with a 2-kHz, single-ended input signal used for the circuit in Figure 44.



SNR = 79.9 dB, THD = -90 dB, SINAD = 79.4 dB

**Figure 45. Test Results for the ADS7057 With a 2-kHz, Single-Ended Input**

## 10 Power Supply Recommendations

### 10.1 AVDD and DVDD Supply Recommendations

The device has two separate power supplies: AVDD and DVDD.

AVDD powers the analog blocks and is also used as the reference voltage for the analog-to-digital conversion. Use a low-noise, low-dropout regulator (LDO) or a discrete reference to supply AVDD (see the [Reference](#) and [Application Information](#) sections). Always set the AVDD supply to be greater than or equal to the maximum input signal to avoid code saturation. Decouple the AVDD pin to the GND pin with a 3.3- $\mu$ F ceramic decoupling capacitor.

DVDD is used for the interface circuits. Decouple the DVDD pin to the GND pin with a 1- $\mu$ F ceramic decoupling capacitor. [图 46](#) shows the decoupling recommendations.

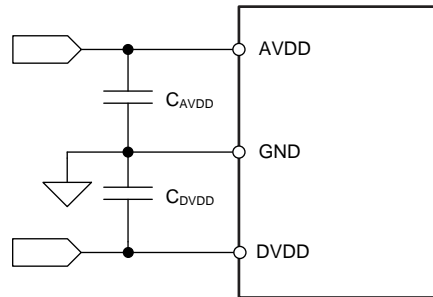


图 46. Power-Supply Decoupling

### 10.2 Optimizing Power Consumed by the Device

In order to best optimize the power consumed by the device, use the following design considerations:

- Keep the analog supply voltage (AVDD) in the specified operating range and equal to the maximum analog input voltage.
- Keep the digital supply voltage (DVDD) in the specified operating range and at the lowest value supported by the host controller.
- Reduce the load capacitance on the SDO output.
- Run the device at the optimum throughput. Power consumption reduces proportionally with the throughput.

#### 10.2.1 Estimating Digital Power Consumption

The current consumption from the DVDD supply depends on the DVDD voltage, the load capacitance on the SDO pin ( $C_{\text{LOAD-SDO}}$ ), and the output code, and can be calculated as:

$$I_{\text{DVDD}} = C_{\text{LOAD-SDO}} \times V \times f$$

where:

- $C_{\text{LOAD-SDO}}$  = Load capacitance on the SDO pin
  - $V$  = DVDD supply voltage
  - $f$  = Frequency of transitions on the SDO output
- (2)

The number of transitions on the SDO output depends on the output code, and thus changes with the analog input. The maximum value of  $f$  occurs when data output on the SDO change on every SCLK (that is, for output codes of 2AAAh or 1555h). With an output code of 2AAAh or 1555h,  $f = 17.5$  MHz and when  $C_{\text{LOAD-SDO}} = 20$  pF and  $\text{DVDD} = 1.8$  V,  $I_{\text{DVDD}} = 630$   $\mu$ A.

## 11 Layout

### 11.1 Layout Guidelines

图 47 shows a typical connection diagram for the ADS7057.

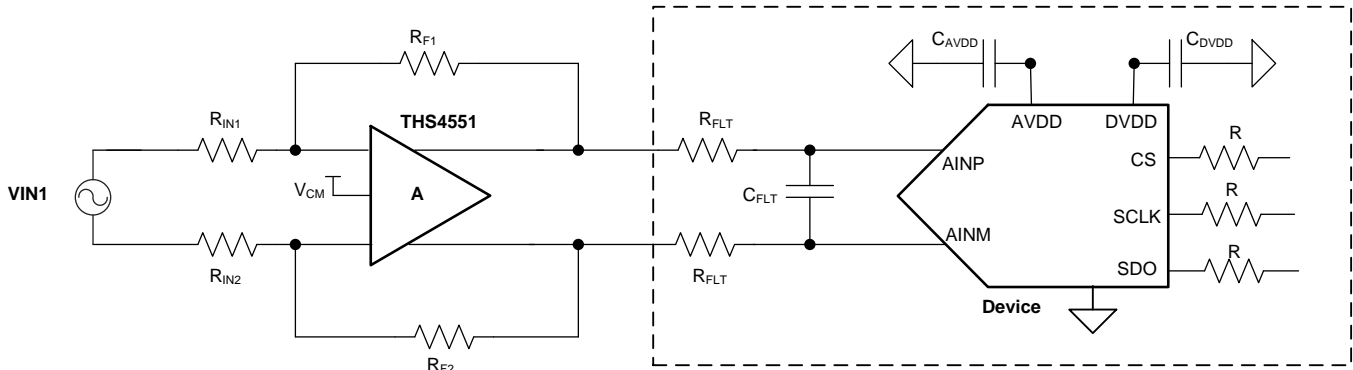


图 47. Typical Connection Diagram

图 48 depicts a board layout example for the device for the typical connection diagram in 图 47. The key considerations for layout are:

- Use a solid ground plane underneath the device and partition the PCB into analog and digital sections
- Avoid crossing digital lines with the analog signal path and keep the analog input signals and the reference input signals away from noise sources.
- The power sources to the device must be clean and well-bypassed. Use  $C_{AVDD}$  decoupling capacitors in close proximity to the analog (AVDD) power-supply pin.
- Use a  $C_{DVDD}$  decoupling capacitor close to the digital (DVDD) power-supply pin.
- Avoid placing vias between the AVDD and DVDD pins and the bypass capacitors.
- Connect the ground pin to the ground plane using a short, low-impedance path.
- Place the charge kickback filter components close to the device.

Among ceramic surface-mount capacitors, COG (NPO) ceramic capacitors are recommended because these components provide the most stable electrical properties over voltage, frequency, and temperature changes.

## 11.2 Layout Example

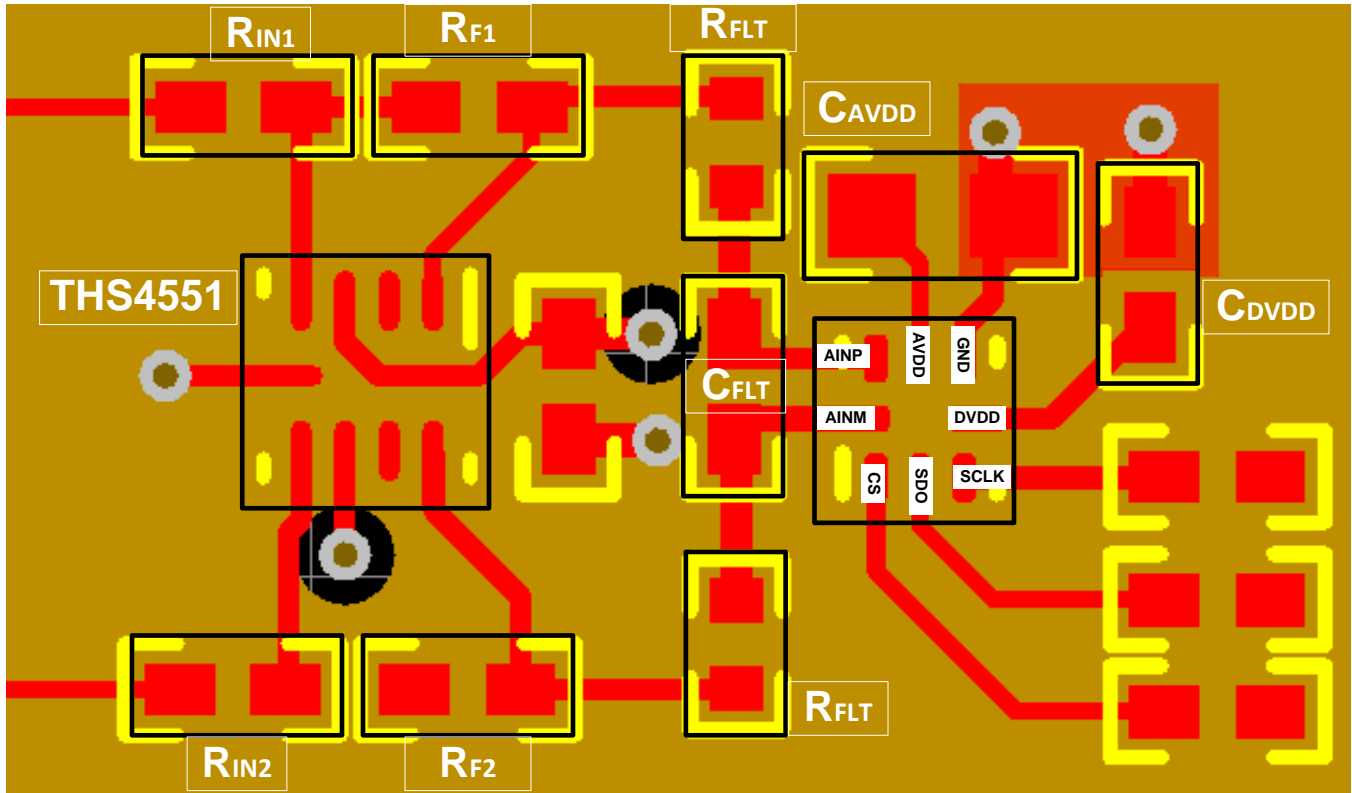


图 48. Example Layout

## 12 器件和文档支持

### 12.1 器件支持

#### 12.1.1 开发支持

[TI 高精度实验室培训视频系列](#)

### 12.2 文档支持

#### 12.2.1 相关文档

请参阅如下相关文档：

输入驱动器放大器（单端输入）：

- [《OPAx836 极低功耗、轨至轨输出、负轨输入、电压反馈运算放大器》](#)
- [THS403x 100MHz 低噪声高速放大器](#)
- [《OPAx365 50MHz、零交叉、低失真、高 CMRR、RRI/O、单电源运算放大器》](#)

输入驱动器放大器（全差分输入）：

- [THS4551 低噪声 150MHz 全差分精密放大器](#)
- [《OPAx836 极低功耗、轨至轨输出、负轨输入、电压反馈运算放大器》](#)

基准驱动器：

- [《REF19xx 低漂移、低功率、双路输出、 \$V\_{REF}\$  和  \$V\_{REF}/2\$  电压基准》](#)
- [《具有集成 ADC 驱动器缓冲器的 REF61xx 高精度电压基准》](#)

类似器件：

- [《ADS7042 超低功耗、超小尺寸、12 位、1MSPS、SAR ADC》](#)
- [《ADS7049-Q1 小型低功耗 12 位、2MSPS SAR ADC》](#)

参考设计：

- [TI 设计：采用 73dB SNR、7.5MSPS 时间交织 SAR ADC 且适用于成像应用的模拟前端参考设计](#)
- [针对双极信号采用运算放大器和 FDA 的单端到差分](#)

### 12.3 接收文档更新通知

要接收文档更新通知，请导航至 [TI.com](http://TI.com) 上的器件产品文件夹。单击右上角的 [通知我](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 12.4 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商“按照原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

**TI E2E™ 在线社区** [TI 的工程师对工程师 \(E2E\) 社区](#)。此社区的创建目的在于促进工程师之间的协作。在 [e2e.ti.com](http://e2e.ti.com) 中，您可以咨询问题、分享知识、拓展思路并与同行工程师一道帮助解决问题。

**设计支持** [TI 参考设计支持](#) 可帮助您快速查找有帮助的 E2E 论坛、设计支持工具以及技术支持的联系信息。

### 12.5 商标

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

### 12.6 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。



## 12.7 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

### 13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知和修订此文档。如欲获取此产品说明书的浏览器版本，请参阅左侧的导航。

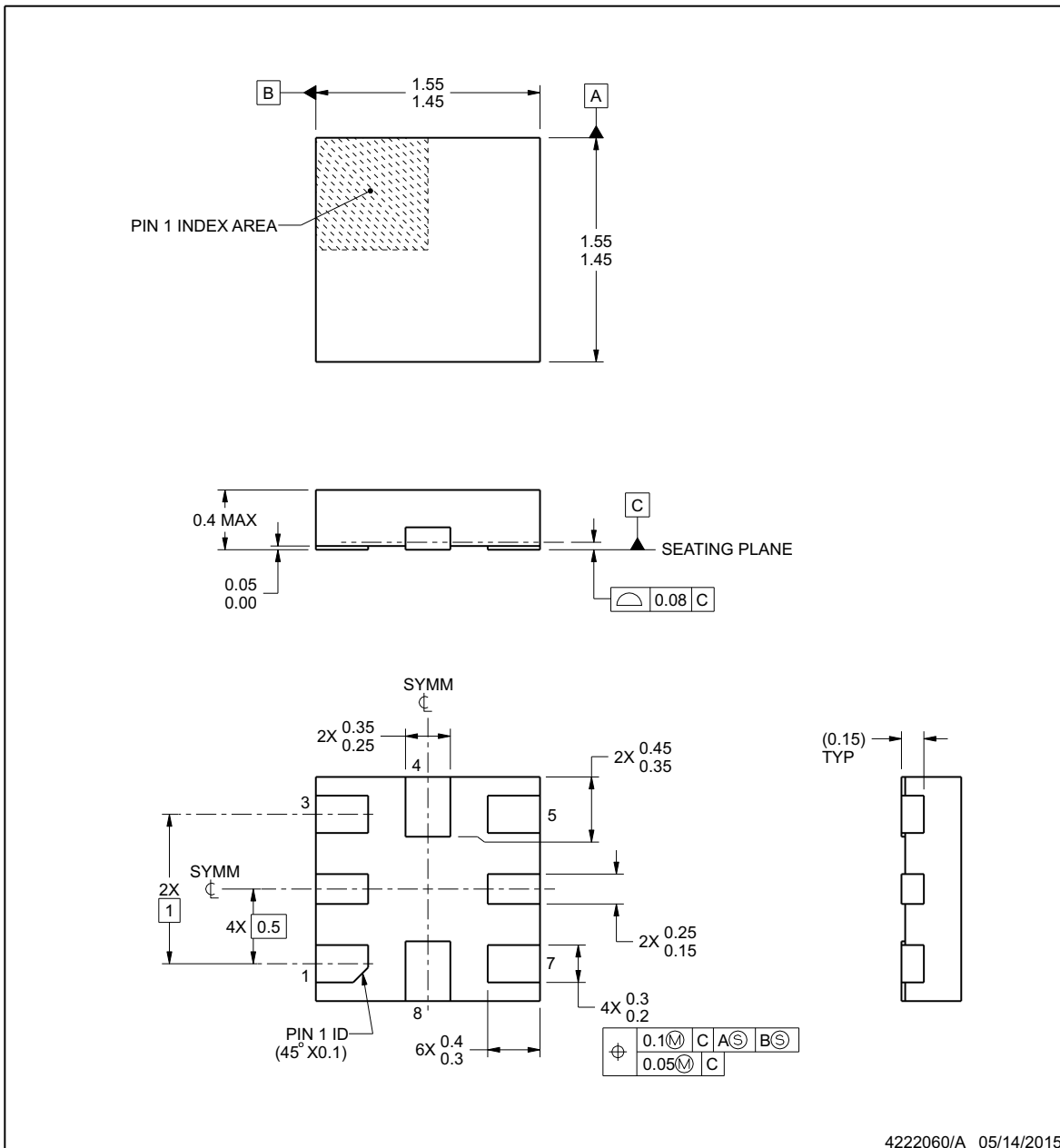


RUG0008A

PACKAGE OUTLINE

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

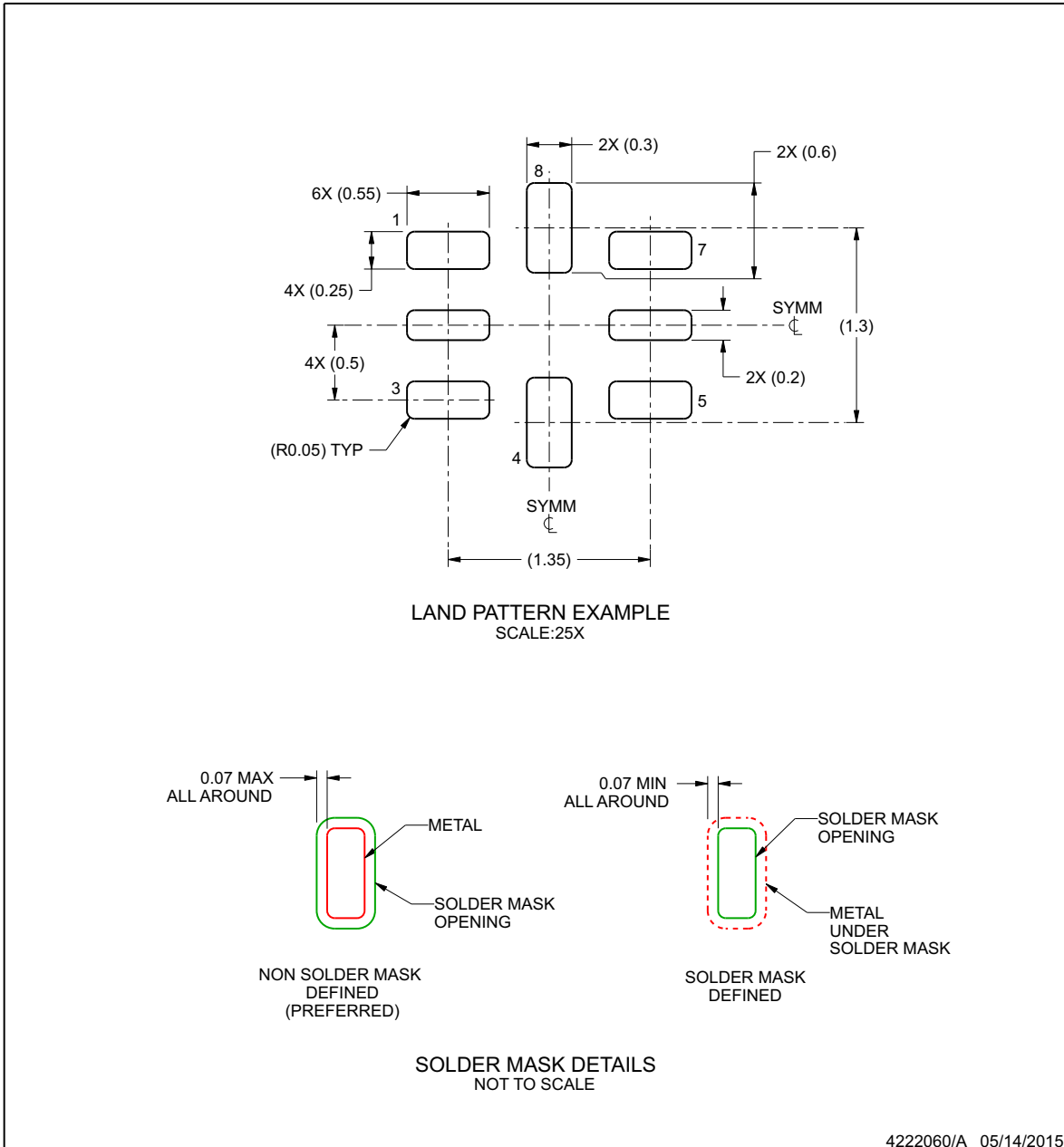
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

RUG0008A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4222060/A 05/14/2015

NOTES: (continued)

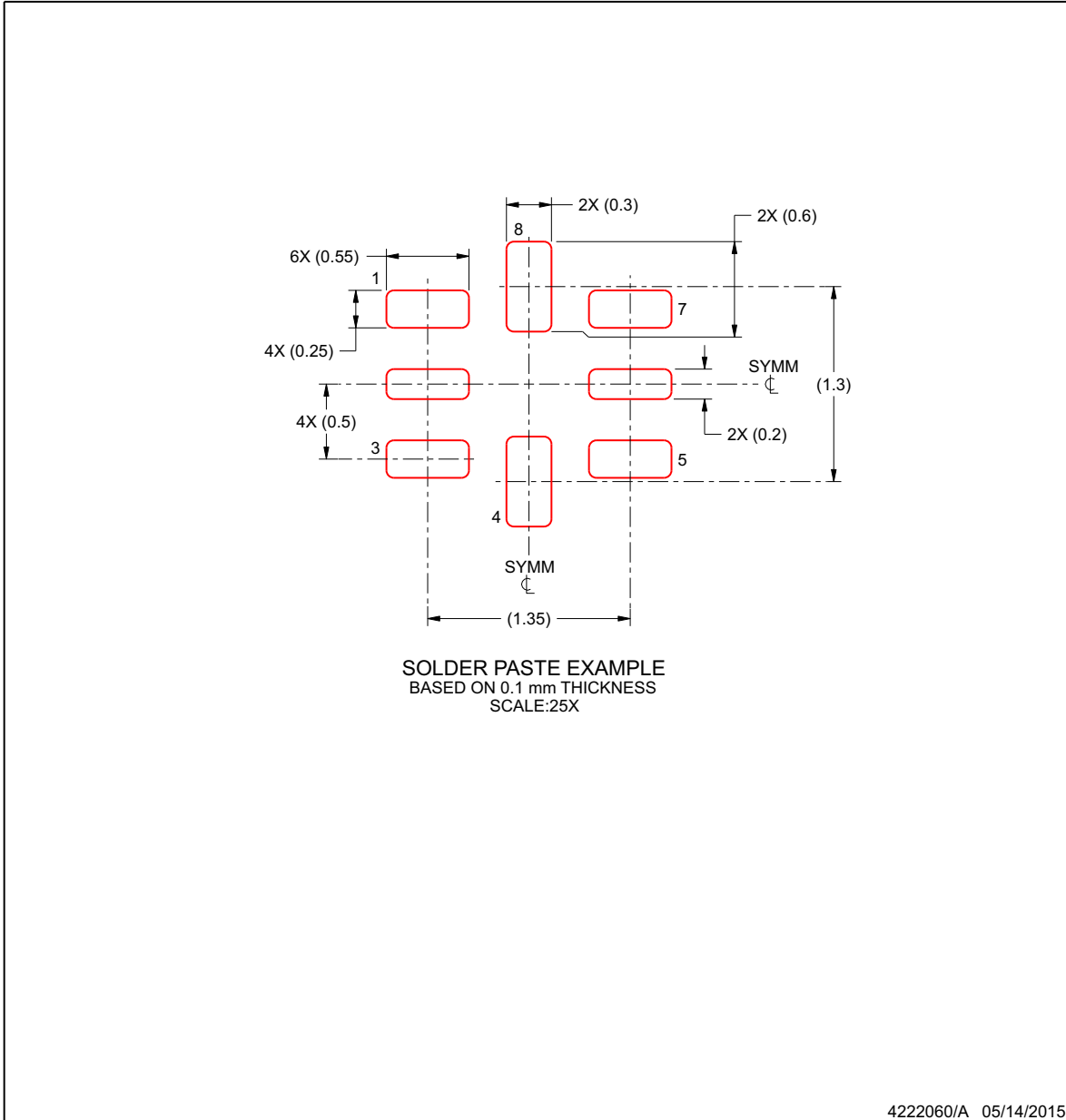
3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

EXAMPLE STENCIL DESIGN

RUG0008A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ADS7057IRUGR	ACTIVE	X2QFN	RUG	8	3000	RoHS & Green	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	9P	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ADS7057IRUGR	X2QFN	RUG	8	3000	180.0	8.4	1.6	1.6	0.66	4.0	8.0	Q2

TAPE AND REEL BOX DIMENSIONS



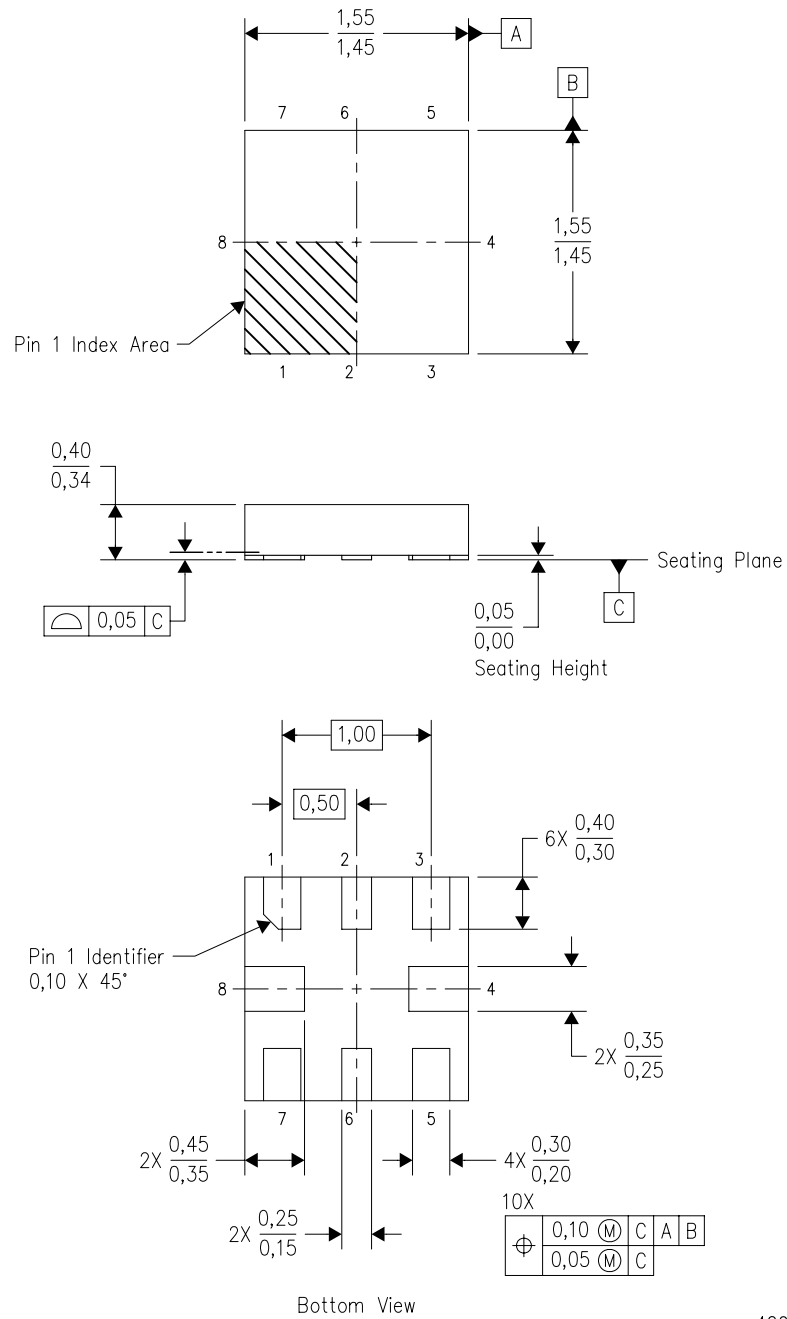
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ADS7057IRUGR	X2QFN	RUG	8	3000	183.0	183.0	20.0



RUG (S-PQFP-N8)

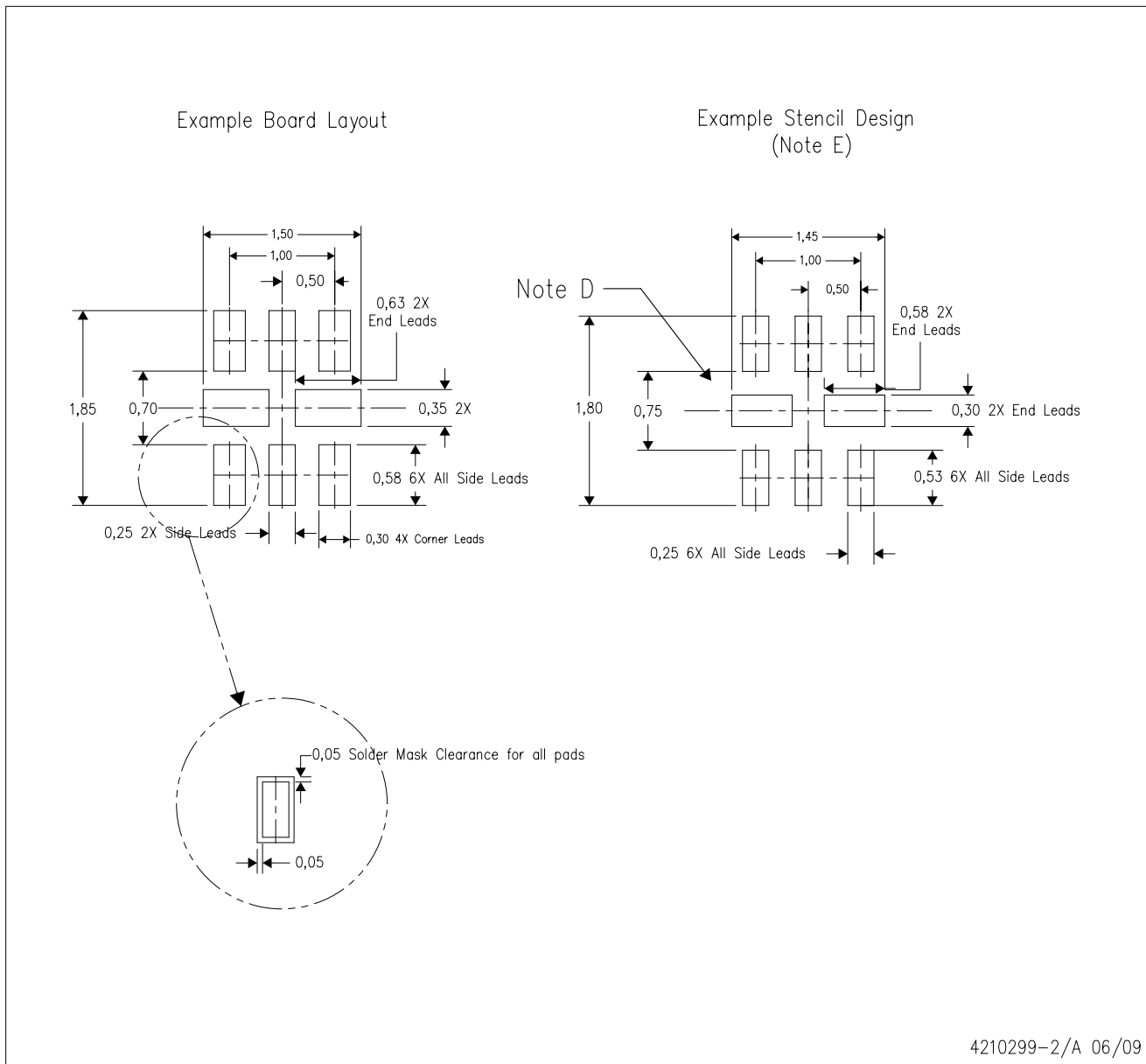
PLASTIC QUAD FLATPACK



4208528-2/B 04/2008

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - D. This package complies to JEDEC MO-288 variation X2ECD.

RUG (R-PQFP-N8)



4210299-2/A 06/09

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
  - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
  - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

## 重要声明和免责声明

TI 均以“原样”提供技术性及其可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证其中不含任何瑕疵，且不做任何明示或暗示的担保，包括但不限于对适销性、适合某特定用途或不侵犯任何第三方知识产权的暗示担保。

所述资源可供专业开发人员应用TI 产品进行设计使用。您将对以下行为独自承担全部责任：(1) 针对您的应用选择合适的TI 产品；(2) 设计、验证并测试您的应用；(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。所述资源如有变更，恕不另行通知。TI 对您使用所述资源的授权仅限于开发资源所涉及TI 产品的相关应用。除此之外不得复制或展示所述资源，也不提供其它TI 或任何第三方的知识产权授权许可。如因使用所述资源而产生任何索赔、赔偿、成本、损失及债务等，TI 对此概不负责，并且您须赔偿由此对TI 及其代表造成的损害。

TI 所提供产品均受TI 的销售条款 (<http://www.ti.com.cn/zh-cn/legal/termsofsale.html>) 以及ti.com.cn上或随附TI产品提供的其他可适用条款的约束。TI提供所述资源并不扩展或以其他方式更改TI 针对TI 产品所发布的可适用的担保范围或担保免责声明。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122  
Copyright © 2020 德州仪器半导体技术（上海）有限公司